

J. S. University, Shikohabad



Diploma

THREE YEAR DIPLOMA COURSE IN
Electronics Engineering

Scheme
&
Syllabus

[Effective from the session 2015-16]

**STUDY AND EVALUATION SCHEME FOR
THREE YEAR DIPLOMA COURSE IN
ELECTRONICS ENGG.**

SEMESTER - First

S.No.	Subject Code	Name of Subject	Periods Per Week				Evaluation Scheme			
			L	T	P	D	Sessional	End Exam	Total	Duration
THEORY SUBJECT										
1	DAS-11	Professional Communication	4	1	-	-	20	50	70	2.5
2	DAS-12	Applied Mathematics-I	4	1	-	-	20	50	70	2.5
3	DAS-13	Applied Physics-I	4	1	-	-	20	50	70	2.5
4	DAS-14	Applied Chemistry	4	1	-	-	20	50	70	2.5
5	DEE-11	Electrical & Electronics Engineering Material	4	1	-	-	20	50	70	2.5

PRACTICA/DRAWING SUBJECTS

5	DWP-11P	Workshop Practice	-	-	10	-	30	60	90	3
6	DAS-11P	Professional Communication	-	-	4	-	20	40	60	3
7	DAS-14P	Applied Chemistry	-	-	4	-	20	40	60	3
8	DGD-10	Games//Social and Cultural Activities + Discipline (15 + 10)							25	
Grand Total									585	

NOTE:- (1) Each period will be 50 minutes duration.

(2) Each session will be of 16 weeks.

(3) Effective teaching will be at least 14 weeks.

(4) Remaining periods will be utilised for revision etc.

**STUDY AND EVALUATION SCHEME FOR
THREE YEAR DIPLOMA COURSE IN
ELECTRONICS ENGG..**

SEMESTER - Second

S.No.	Subject Code	Name of Subject	Periods Per Week				Evaluation Scheme			
			L	T	P	D	Sessional	End Exam	Total	Duration
THEORY SUBJECT										
1	DAS-22	Applied Mathematics-II	4	1	-	-	20	50	70	2.5
2	DAS-23	Applied Physics-II	4	1	-	-	20	50	70	2.5
3	DEE-21	Basic Electrical Engg	4	1	-	-	20	50	70	2.5
4	DEC-21	Electronics - I	4	1	-	-	20	50	70	2.5
5	DDW-21	Engineering Drawing	-	-	-	8	20	50	70	3
PRACTICA/DRAWING SUBJECTS										
6	DAS-23P	Applied Physics-II Lab	-	-	4	-	20	40	60	3
7	DEE-21P	Basic Electrical Engg Lab	-	-	4	-	30	60	90	3
8	DEC-21P	Electronics – I Lab	-	-	4	-	30	60	90	3
9	DGD-20	Games//Social and Cultural Activities + Discipline (15 + 10)							25	
Grand Total								615		

NOTE:- (1) Each period will be 50 minutes duration.

(2) Each session will be of 16 weeks.

(3) Effective teaching will be at least 14 weeks.

(4) Remaining periods will be utilised for revision etc.

**STUDY AND EVALUATION SCHEME FOR
THREE YEAR DIPLOMA COURSE IN
ELECTRONICSENGG.**

SEMESTER - THIRD

S.No.	Subject Code	Name of Subject	Periods Per Week				Evaluation Scheme			
			L	T	P	D	Sessional	End Exam	Total	Duration
THEORY SUBJECT										
1	DAS-31	Applied Mathematics-III	4	1	-	-	20	50	70	2.5
2	DEE-33	Electrical Engineering-II	4	1	-	-	20	50	70	2.5
3	DEC-31	Industrial Electronics & Transducers.	4	1	-	-	20	50	70	2.5
4	DCS-32	Programming In C & C++	4	1	-	-	20	50	70	2.5
PRACTICA/DRAWING SUBJECTS										
5	DEE-33P	Electrical Engineering-II Lab	-	-	4	-	20	40	60	3
6	DEC-31P	Industrial Electronics & Transducers. Lab	-	-	4	-	20	40	60	3
7	DCS-32P	Programming In C & C++ Lab	-	-	4	-	30	40	70	3
8	DEC-35P	Electronics Workshop	-	-	4	-	20	40	60	3
9	DGD-30	Games//Social and Cultural Activities + Discipline (15 + 10)							25	
Grand Total									555	

NOTE:- (1) Each period will be 50 minutes duration.

(2) Each session will be of 16 weeks.

(3) Effective teaching will be at least 14 weeks.

(4) Remaining periods will be utilised for revision etc.

**STUDY AND EVALUATION SCHEME FOR
THREE YEAR DIPLOMA COURSE IN
ELECTRONICS ENGG.**

SEMESTER - FOURTH

S.No.	Subject Code	Name of Subject	Periods Per Week				Evaluation Scheme			
			L	T	P	D	Sessional	End Exam	Total	Duration
THEORY SUBJECT										
1	DEC-42	Networks, Filters & Transmission Lines	4	1	-	-	20	50	70	2.5
2	DEC-43	Electronic Devices And Circuits	4	1	-	2	20	50	70	3
3	DEC-44	Principles of Communication Engineering	4	1	-	-	20	50	70	2.5
4	DEC-45	Principles of Digital Electronics	4	1	-	-	20	50	70	2.5

PRACTICA/DRAWING SUBJECTS

5	DEC-42P	Networks, Filters & Transmission Lines Lab	-	-	4	-	20	40	60	3
6	DEC-43P	Electronic Devices And Circuits Lab	-	-	4	-	20	40	60	3
7	DEC-44P	Principles of Comm. Engineering Lab	-	-	4	-	20	40	60	3
8	DEC-45P	Principles of Digital Electronics Lab	-	-	4	-	20	40	60	3
9	DGD-40	Games//Social and Cultural Activities + Discipline (15 + 10)							25	
Grand Total									545	

NOTE:- (1) Each period will be 50 minutes duration.

(2) Each session will be of 16 weeks.

(3) Effective teaching will be at least 14 weeks.

(4) Remaining periods will be utilised for revision etc.

**STUDY AND EVALUATION SCHEME FOR
THREE YEAR DIPLOMA COURSE IN
ELECTRONICS ENGG. (E.C.)**

SEMESTER - Fifth

S.No.	Subject Code	Name of Subject	Periods Per Week				Evaluation Scheme			
			L	T	P	D	Sessional	End Exam	Total	Duration
THEORY SUBJECT										
1	DIM-51	Industrial Management and Entrepreneurship Development	4	1	-	-	20	50	70	2.5
2	DEC-51	Electronic Instruments And Measurement	4	1	-	-	20	50	70	2.5
3	DEC-52	Audio And Video Engg.	4	1	-	-	20	50	70	2.5
4	DEC-53	Microprocessor And Application.	4	1	-	-	20	50	70	2.5
PRACTICA/DRAWING SUBJECTS										
5	DFE-51P	Field Exposure	-	-	10	-	20	50	70	3
6	DEC-51P	Electronic Instruments And Measurement Lab	-	-	4	-	20	50	70	3
7	DEC-52P	Audio And Video Engg. Lab	-	-	4	-	20	40	60	3
	DEC-53P	Microprocessor And Application. Lab					20	40	60	
8	DGD-50	Games//Social and Cultural Activities + Discipline (15 + 10)							25	
Grand Total									565	

NOTE:- (1) Each period will be 50 minutes duration.

(2) Each session will be of 16 weeks.

(3) Effective teaching will be at least 14 weeks.

(4) Remaining periods will be utilised for revision etc.

**STUDY AND EVALUATION SCHEME FOR
THREE YEAR DIPLOMA COURSE IN
ELECTRONICS ENGG. (E.C.)**

SEMESTER - Sixth

S.No.	Subject Code	Name of Subject	Periods Per Week				Evaluation Scheme			
			L	T	P	D	Sessional	End Exam	Total	Duration
THEORY SUBJECT										
1	DDM-61	Environmental Education And Disaster Management	4	1	-	-	20	50	70	2.5
2	DEC-61	Microwave & Radar Engg.	4	1	-	-	20	50	70	2.5
3	DEC-62	Modern Communication System	4	1	-	-	20	50	70	2.5
4	DEC-63	Optical Fiber Engg.	4	1	-	-	20	50	70	2.5
PRACTICA/DRAWING SUBJECTS										
6	DEC-61P	Project	-	-	4	-	50	100	150	3
7	DEC-62P	Modern Communication System Lab	-	-	4	-	30	60	90	3
8	DEC-63P	Optical Fiber Engg. Lab	-	-	4	-	30	60	90	3
9	DGD-60	Games//Social and Cultural Activities + Discipline (15 + 10)							25	
Grand Total									635	

NOTE:- (1) Each period will be 50 minutes duration.

(2) Each session will be of 16 weeks.

(3) Effective teaching will be at least 14 weeks.

(4) Remaining periods will be utilised for revision etc.

SEMESTER-I

[DAS-11] Professional Communication

1. PART I - COMMUNICATION IN ENGLISH

1.1 Concept of communication, importance of effective communication, types of communication, formal, informal, verbal and nonverbal, spoken and written. Techniques of communication, listening, reading, writing and speaking,

Barriers in communication, Modern tools of communication-Fax, e-mail, Telephone, telegram, etc.

1.2 Technical communication Vs. General Communication: Development of comprehension and knowledge of English through the study of text material and language exercises based on the prescribed text book of English.

1.3 Development of expression through:

1.3.1 Paragraph writing, Essay writing, Proposal writing.

1.3.2 Business and personal correspondence (Letters):Kinds of letters:-Official, demi-official, unofficial , for reply or inreply, quotation, tender and order giving letters. Application for a job, Resume.

1.3.3 Report writing and Note making and minutes writing.

1.4 Functional Grammar: Study of sentences and parts of speech(word class), Preposition, Verb, Articles, Abbreviations.

1.5 Vocabulary Building: Homophones, One word substitution,Idioms and Phrases.

1.6 Composition on narrative, descriptive, imaginative, argumentative, discussion and factual topics.

2. PART II - COMMUNICATION IN HINDI

2.1 Development of comprehension and knowledge of Hindi usage through rapid reading and language exercises based on prescribed text material developed by IRDT.

2.2 Development of expression through ;Letter writing in Hindi:Kinds of letters:-Official, demi-official, unofficial , for reply or inreply, quotation, tender and order giving letters,Application for a job, Press release in Hindi, Report writing.

Note: Paper should be in two parts, part I - English and part II -Hindi.

REFERENCE BOOKS

1. Bookshelf worksheet of Professional Communication, New Delhi: Bookshelf 2008
2. Functional Skills in language and literature by R. P. Singh, New Delhi: Oxford University Press.
3. Oxford English Hindi English Dictionary, New Delhi: Oxford 2008

[DAS-11P]Professional Communication Lab

For the practice/exercise the following is suggested:

1. A. Phonetic transcription

B. Stress and intonation:

(At least 10 word for writing and 10 word for pronunciation)

2. ASSIGNMENT: (Written Communication)

Two assignments of approximately 400 word each decided by the teacher concerned.

THE FOLLOWING MODEL IS PROPOSED:

1. A picture/photograph

2. An opening sentence or phrase

3. A newspaper/magazine clipping or report

4. Factual writing which should be informative or argumentative.

(The students may refer to "Bookshelf worksheet" for technical communication)

3. Oral Conversation:

1. Short speeches/declamation: Bid farewell, felicitate somebody, celebrate a public event, and Offer condolences

2. Debate on current problems/topics

3. Mock Interview: Preparation, Unfolding of personality and expressing ideas effectively

4. Group discussion on current topics/problems

5. Role Play/ general conversation: Making polite enquiries at Railway Station, Post Office, Banks and other Public places, replying to such enquiries, enquiring about various goods sold in the market and discussing their prices.

Complaining about service at Hotel, restaurant, Offering apologies in reply to such complaints, complain to a company about a defective product you have brought, reply to such complaints.

6. Presentation skill, Use of OHP and LCD.

7. through drilling of model words involving different phonetic symbols (Vowels, Consonants, and Diphthongs).

4. Aural : Listening to conversation/talk/reading of short passage and then writing down the relevant or main points in the specified number of words and answering the given questions. The assignments/project work are to be evaluated by the internal/ external examiner. The distribution of 30 marks e.g.

10 marks for assignment (Given by subject teacher assessmental marks)

10 marks for conversation and viva-voce

10 marks for phonetic transcription

[DAS-12] APPLIED MATHEMATICS - I

Unit -1: Algebra-I

1. Arithmetic Mean: nth term, sum, Mean
2. Geometric Mean: nth term, sum, Mean
3. Binomial Theorem for positive, negative and fractional index (without proof)
4. Determinants: Elementary properties of determinants of order 2 and 3, system of linear equations and solution, Cramer's Rule

. Unit -2: Algebra-II

1. Vector Algebra: Dot and cross product, Scalar and vector triplet product
2. Complex Numbers: Representation, Modulus and Amplitude, De-Moivre theorem application in solving algebraic equations.

Unit -3: Trigonometry

1. Relation between sides and angles of a triangle: Statement of various formula showing relationship between sides and angles of a triangle.
2. Inverse Circular Functions

Unit -4: Differential Calculus-I

1. Functions, limits, continuity, elementary methods of finding limit (right and left)
2. Differentiability, method of finding derivatives, functions of a function, Logarithmic Differentiation, Differentiation of Implicit functions.

Unit -5: Differential Calculus-II

1. Higher order derivatives
2. Derivatives of Special Functions (Exponential, Logarithmic, and Inverse circular functions)
3. Application: Finding Tangent, Rate Measure, Velocity and Acceleration

[DAS-13]APPLIED PHYSICS-I

Topic Wise Distribution

S.no.	Topics	Marks Distribution
1	Unit &Dimensions	4
2	Errors & Measurement	4
3	Heat & Thermodynamics	5
4	Friction	4
5	Circular Motion	5
6	Motion of Planets & satellites	5
7	Dynamic of Rigid Body	6
8	Fluid Mechanics	6
9	Harmonic Motion	6
10	Acoustics	5
	Total	50

Detailed Contents

1. UNIT AND DIMENSION

Physical quantity and its types, Unit and its types, Definition of SI units, Dimensions of physical quantities, Dimensional formula and dimensional equation, Principle of homogeneity and its applications, Limitations of dimensional analysis

2. ERRORS AND MEASUREMENTS

Errors, Accuracy and Precision, Types of errors in measurement, Combination of errors, Significant figures, Rounding off

3. HEAT AND THERMODYNAMICS

Modes of heat transfer, Coefficient of thermal conductivity, Conduction through compound medium, Isothermal and Adiabatic process, Zeroth and First law of thermodynamics

4. FRICTION

Introduction, Physical significance of friction, Advantage and disadvantage of friction and its role in daily life, Coefficient of static and dynamic friction and their measurement, Angle of friction, Angle of repose, Motion of a body on a inclined plane

5. CIRCULAR MOTION

Uniform circular motion, Angular velocity and acceleration, centripetal acceleration, Relation between linear and angular velocity and acceleration, Centripetal and centrifugal forces, Practical applications of centripetal forces

6. MOTION OF PLANETS AND SATELLITES

Gravitational force, Acceleration due to gravity and its variation with respect to height and depth from earth, Kapler's law, Escape and orbital velocity, Time period of satellite, Geo-stationary satellite

7. DYNAMIC OF RIGID BODY

Rigid body, Rotational motion, Moment of inertia, Theorems (parallel and perpendicular) of moment of inertia, Expression of M.I. of regular bodies (lamina ,disc, sphere, cylindrical), Radius of gyration, Angular momentum, Conservation of angular momentum, Torque, Rotational kinetic energy, Rolling of sphere on the slant plane

8. FLUID MECHANICS

Surface tension, Capillary action and determination of surface tension from capillary rise method, Equation of continuity, Bernoulli's theorem and its application, Stream line and Turbulent flow, Viscosity, Stokes law, Reynold's number

9. HARMONIC MOTION

Periodic function, Characteristics of SMH, Equation of SMH and determination of velocity and acceleration, Simple pendulum and derivation of its periodic time, Spring-mass system, Energy conservation of SHM, Concept of phase, Definition of free, forced, damped and un-damped vibrations, Resonance and its application, Q-factor

10. ACOUSTICS

Definition of pitch, loudness, quality and intensity of Sound waves, Echo, Reverberation and reverberation time, Sabine's formula without derivation, Acoustics of building defects and remedy.

[DAS-14] APPLIED CHEMISTRY

1. ATOMIC STRUCTURE:

Basic concept of atomic structure, Matter wave concept, Quantum number, Heisenberg's Uncertainty Principle, Shapes of orbitals.

2. CHEMICAL BONDING:

Covalent bond, Ionic & Co-ordinate, Hydrogen bonding, Valence bond theory, Hybridisation, VSEPR theory, Molecular orbital theory

3. CLASSIFICATION OF ELEMENTS:

Modern classification of elements (s p d and f block elements), Periodic properties : Ionisation potential, electronegativity, Electron affinity.

4. ELECTRO CHEMISTRY-I:

Arrhenius Theory of electrolytic dissociation, Transport number, Electrolytic conductance, Ostwald dilution law. Concept of Acid and base: Bronsted, Arrhenius and Lewis theory. Concept of pH based numerical. Buffer solutions, Indicators, Solubility product, Common ion effect with their application,

5. ELECTRO CHEMISTRY-II:

Redox reactions, Electrode potential (Nernst Equation), Electro-chemical cell (Galvanic and Electrolytic). EMF of a cell and free energy change, Standard electrode potential, Electro chemical series and its application. Chemical and Electrochemical theory of corrosion, Galvanic Series. Prevention of corrosion by various method.

6. CHEMICAL KINETICS:

Law of mass action, order and molecularity of reaction. Activation energy, rate constants, 1st order reactions and 2nd order reactions.

7. CATALYSIS:

Definition Characteristics of catalytic reactions, Catalytic promoters and poison, Autocatalysis and Negative catalysis, Theory of catalysis, Application.

8. SOLID STATE:

Types of solids (Amorphous and Crystalline), Classification (Molecular, Ionic, Covalent, Metallic), Band theory of solids (Conductors, Semiconductors and Insulators), types of Crystals, FCC, BCC, Crystal imperfection.

9. FUELS:

Definition, its classification, high & low Calorific value. Determination of calorific value of solid and liquid fuels by Bomb calorimeter. Liquid fuel - Petroleum and its refining, distillate of petroleum (Kerosene oil, Diesel and Petrol), Benzol and Power alcohol. Knocking, Anti-knocking agents, Octane number and Cetane number. Cracking and its type, Gasolining from hydrogenation of coal (Bergius process and Fischer Tropsch's process) Gaseous Fuel - Coal gas, Oil gas, Water gas, Producer gas, Bio gas, LPG and CNG. Numerical Problems based on topics

10. WATER TREATMENT:

Hardness of water, Its limits and determination of hardness of water by EDTA method. Softening methods (Only Soda lime, Zeolite and Ion exchange resin process). Disadvantage of hard water in different industries, scale and sludge formation, Corrosion, Caustic embrittlement, priming and foaming in boilers. Disinfecting of Water By Chloramine-T, Ozone and Chlorine. Advantage and disadvantage of chlorination, Industrial waste and sewage, Municipality waste water treatment, Definition of BOD and COD. Numerical Problems based on topics.

11. COLLOIDAL STATE OF MATTER:

Concept of colloidal and its types, Different system of colloids, Dispersed phase and dispersion medium. Methods of preparation of colloidal solutions, Dialysis and electrodialysis. Properties of colloidal solution with special reference to absorption, Brownian Movement, Tyndall effect, Electro phoresis and coagulation. Relative stability of hydrophilic and hydrophobic colloids. Protection and protective colloids. Emulsion, Types, preparation, properties and uses. Application of colloids chemistry in different industries.

12. LUBRICANTS:

Definition, classification, Necessity and various kinds of lubricants. Function and mechanism of action of lubricants and examples. Properties of lubricants, Importance of additive compounds in lubricants, Synthetic lubricants and cutting fluids. Industrial application, its function in bearing.

13. HYDROCARBONS:

- A. Classification and IUPAC nomenclature of organic compounds homologous series (Functional Group)
- B. Preparation, properties and uses of Ethane, Ethene, Ethyne (Acetylene), Benzene and Toluene.

14. ORGANIC REACTIONS & MECHANISM:

- 1. Fundamental aspects -

- A. Electrophiles and nucleophiles, Reaction Intermediates, Free radical, Carbocation, Carbanion
- B. Inductive effect, Mesomeric effect, Electromeric effect.

- 2.A. Mechanism of addition reaction (Markovnikov's Rule, Cyanohydrin and Peroxide effect),

- B. Mechanism of Substitution reactions; (Nucleophilic) hydrolysis of alkyl halide, electrophilic substitution halogenation, Sulphonation, Nitration and Friedel-Craft reaction.

- C. Mechanism of Elimination reaction - Dehydration of primary alcohol, Dehydrohalogenation of primary alkyl halide.

15. POLYMERS :

- 1. Polymers and their classification. Average degree of polymerisation, Average molecular weight, Free radical polymerisation (Mechanisms)

- 2. Thermosetting and Thermoplastic resins -

- A. Addition polymers and their industrial application - Polystyrene, PVA, PVC, PAN, PMMA, Buna-S, Buna-N, Teflon.

- B. Condensation polymer and their industrial application : Nylon 6, Nylon 6,6, Bakelite, Melamine formaldehyde, Urea formaldehyde, Terylene or Decron, Polyurethanes.

- 3. General concept of Bio polymers, Biodegradable polymers and inorganic polymers (Silicon).

16. SYNTHETIC MATERIALS:

- A. Introduction - Fats and Oils

- B. Saponification of fats and oils, Manufacturing of soap.

C. Synthetic detergents, types of detergents and its manufacturing.

3. EXPLOSIVES: TNT, RDX, Dynamite.

4. Paint and Varnish

[DAS-14P] CHEMISTRY LAB

1. To analyse inorganic mixture for two acid and basic radicals from following radicals:

A. Basic Radicals : NH_4^+ , Pb^{++} , Cu^{++} , Bi^{+++} , Cd^{++} , As^{+++} , Sb^{+++} , Sn^{++} , Al^{+++} , Fe^{+++} , Cr^{+++} , Mn^{++} , Zn^{++} , Co^{++} , Ni^{++} , Ba^{++} , Sr^{++} , Ca^{++} , Mg^{++}

B. Acid Radicals : CO_3^{--} , S^{--} , SO_3^{--} , CH_3COO^- , NO_2^- , NO_3^- , Cl^- , Br^- , I^- , SO_4^{--}

2. To determine the percentage of available Chlorine in the supplied sample of Bleaching powder.

3. To determine the total hardness of water sample in terms of CaCO_3 by EDTA titration method using Eriochroma black-T indicator.

4. To determine the strength of given HCl solution by titration against NaOH solution using Phenolphthalein as indicator.

5. To determine the Chloride content in supplied water sample by using Mohr's method.

6. Determination of temporary hardness of water sample by O'Hene's method.

[DEE-11] ELECTRICAL AND ELECTRONICS ENGG. MATERIALS

1. Classification

Classification of materials with reference to their atomic structure.

2. Conducting Materials

(i) Resistivity and factors affecting resistivity, such as temperature, alloying and mechanical stressing.

(ii) Super conductivity and super conducting material.

(iii) Low resistivity materials e.g. copper, aluminium and steel, their general properties as conductors e.g. resistivity, temperature co-efficient, mechanical properties, corrosion, contact resistance and practical application. Uses of mercury as conducting material.

(iv) Comparison of copper, aluminium and steel for various applications as electrical conductor.

(v) Low resistivity copper alloys: brass, bronze (cadmium and beryllium), their practical application.

(vi) High resistivity materials : manganin, constantan, nichrome, carbon, tungsten, their practical applications.

(vii) Electric lamp materials.

(viii) Brush contact materials.

(ix) Soldering materials.

(x) Thermocouple materials, Fuse materials.

3. Insulating Materials

(i) Introduction.

(ii) Properties of insulating material.- Electrical properties: Volume resistivity, Surface resistivity, Dielectric Loss, Dielectric Constant, Dielectric strength.- Mechanical properties:- Mechanical strength- Physical properties :- Hygroscopicity, tensile and compressive strength, Abrasive resistance, brittleness.- Thermal properties - Heat resistance, Classification according to high permissible temperature rise, Effect of over loading on the life of an

electrical appliances, Increase in rating with the use of insulating materials having higher thermal stability, Thermal conductivity.- Chemical properties - Solubility, Chemical resistance, Weather ability.

(iii) Insulating materials and their application-

- Definition and classification- Thermo setting materials e.g. Phenol Formaldehyde, Resins (i.e. Bakelite), Amino resins (Urea formaldehyde and Melamine formaldehyde), Epoxy resins their properties, Applications and Commercial names.- Thermo Plastic materials e.g. Polyvinyl Chloride (P.V.C.), Poly Ethylene Silicons their properties application and commercial names. Brief description of extrusion and moulding process of using plastic

materials in electrical engineering.- Natural Insulating Materials- Mica and Mica products, Asbestos and Asbestos products, Ceramic materials (Porcelain and Steatite), Glass and glass products, Cotton, Silk, Jute, Paper (Dry and impregnated), Rubber Butyl, Mineral and insulating oil for transformer, switch gear, capacitors, high voltage cables, insulating varnishes for coating and impregnation, Enamels for winding wires, Glass fibre sleeves Gaseous Materials e.g. Air, Hydrogen, Nitrogen and SF₆.

4. Magnetic Materials :

(i) Classification of magnetic materials into soft and hard magnetic materials.

(ii) Soft magnetic materials - high silicon alloy steel for transformers and low silicon alloy steel, for electric rotating machine cold rolled grain oriented and non-oriented steel, Nickel iron alloy, soft ferrites, their properties and uses.

(iii) Hard magnetic materials - tungsten steel, chrome steel, cobalt steel, alnico, hard ferrites, their properties and applications.

5. Semiconductor Materials

Introduction, semiconductor and their applications, Different semiconductor materials used in manufacturing various semiconductor (Si & Ge), Material used for electronic components like resistor, capacitor, diode, transistors and inductors.

6. Special Purpose Materials :

Materials used in transistor and IC manufacturing, PC BS, computer memory devices (name of such materials to be added) Ferrous and non ferrous materials. Thermistor, Sensistor, Varistor and their practical applications.

[DWS-11P] WORKSHOP PRACTICE

1. Carpentry Shop :

EX-1 Introduction & demonstration of tools used in carpentry shop and different types of joints, types of wood, seasoning and preservation of wood

EX-2 Planing and sawing practice

EX-3 Making of lap joint

EX-4 Making of mortise and tenon joint

EX-5 Making of any one utility article such as wooden picture frame, hanger, peg, name plate, etc.

2. Painting and Polishing Shop:

EX-1 Introduction of paints, varnishes, Reason for surface preparation, Advantage of painting, other method of surface coating i.e. electroplating etc.

EX-2 To prepare a wooden surface for painting apply primer on one side and to paint the same side. To prepare french polish for wooden surface and polish the other side.

EX-3 To prepare metal surface for painting, apply primer and paint the same.

EX-4 To prepare a metal surface for spray painting, first spray primer and paint the same by spray painting gun and compressor system.

3. Sheet Metal and Soldering Shop :

EX-1 Introduction and Types of sheets, measuring of sheets

EX-2 Study and sketch of various types of stakes/anvil.

EX-3 Introduction & demonstration of tools used in Sheet metal working shop.

EX-4 Cutting, shearing and bending of sheet.

EX-5 To prepare a soap case by the metal sheet.

4. Fitting Shop, Plumbing Shop & Fastening Shop:

EX-1 Study of materials, limits, fits and tolerances.

EX-2 Introduction & demonstration of tools used in Fitting Shop.

EX-3 Hacksawing and chipping of M.S. flat. Filing and squaring of chipped M.S. job. Filing on square or rectangular M.S. piece.

EX-4 Making bolt & nut by tap and die set and make its joints

EX-5 To drill a hole in M.S. Plate and tapping the same to create threads as per need.

5. Foundry Work

Ex-1 Study of metal and non metals

Ex-2 Study & sketch of the foundry tools.

Ex-3 Study & sketch of cupola & pit furnace.

Ex-4 To prepare the green moulding sand and to prepare moulds (single piece and double piece pattern sweep mould)

Ex-5 Casting of non ferrous (lead or aluminium) as per exercise 3.

6. Smithy Shop :

EX-1 Study & Sketch of Tools used in smithy shop.

EX-2 To prepare square or rectangular piece by the M.S. rod.

EX-3 To make a ring with hook for wooden doors.

EX-4 Utility article-to prepare a ceiling fan hook.

7. Welding Shop :

EX-1 Introduction to welding, classification of welding, types of weld joints.

EX-2 Welding practice-gas and electric.

EX-3 Welding for lap joint after preparing the edge.

EX-4 Welding of Butt joint after preparation of the edge.

EX-5 'T' joint welding after preparation of edge.

8. Machine Shop

EX-1 Study & sketch of lathe machine.

EX-1 Study & sketch of grinders, milling M/c, Drilling M/c and CNC Machines

Ex-2 Plain and step turning & knurling practice.

Ex-3 Study and sketch of planing/Shaping machine and to plane a Rectangle of cast iron.

SEMESTER-II

DAS-22 Mathematics - II

Unit -1: Integral Calculus-I

Methods of finding indefinite integral

1. Integration by substitution

2. Integration by parts
3. Integration by partial fraction
4. Integration of special functions

Unit-2: Integral Calculus-II

1. Definite integral: definition and properties, Evaluation of integrals
2. Applications of definite integrals: Finding areas bounded by simple curves, Length of simple curves, Volume of solids of revolution,
3. Numerical Integration: Trapezoidal rule, Simpson's 1/3rd rule and Simpson's 3/8 th rule

Unit-3: Coordinate Geometry-I

1. Circle : Equation of circle in standard form, centre –radius form , diameter form and two intercept form.
2. Standard form of curves and their simple properties:
 - Parabola
 - Ellipse
 - Hyperbola

Unit-4: Coordinate Geometry-II

1. Distance between two points in space , direction cosines and direction ratios, Finding equation of a straight line and shortest distance between two lines.
2. Sphere

[DAS-23] Applied Physics-II

1. Optics

Nature of light, Laws of Reflection and Refraction, Snell's Law, Interference (Constructive and Destructive), Diffraction and Polarization (Concept Only), Law of Malus and Polaroids.
2. Introduction To Fibre Optics :

Critical angle, Total internal reflection, Principle of fibre optics, Optical fibre, Pulse dispersion in step-index fibres, Graded index fibre, Single mode fibre, Optical sensor.
3. Lasers and its Applications

Absorption and Emission of energy by atom, Spontaneous and Stimulated Emission, Population inversion, Main component of laser and types of laser- Ruby Laser, He-Ne laser and their applications. Introduction to MASER.
4. Electrostatics :

Coulomb's Law, Electric field, Electric potential, Potential energy, Capacitor, Energy of a charged capacitor, Effect of dielectric on capacitors.
5. D.C. Circuits

Ohm's Law, Kirchhoff's Law and their simple application, Principle of Wheat Stone bridge and application of this principle in measurement of resistance (Meter bridge and Post Office Box); Carey Foster's bridge, potentiometer.
6. Magnetic Materials and Their Properties:

Dia, Para and Ferro-magnetism, Ferrites, Magnetic Hysteresis Curve and its utility. Basic idea of super conductivity, Meissner's effect.
7. Semiconductor Physics

Concept of Energy bands in solids, classification of solids into conductors, insulators and semiconductors on the basis of energy band structure. Intrinsic and extrinsic semiconductors, Electrons and holes as charge carriers in semiconductors, P-type and N-type semiconductors.
8. Junction Diode and Transistor :

Majority and Minority charge carriers, P-N junction formation, barrier voltage, Forward and reverse biasing of a junction diode, P-N junction device characteristics, Formation of transistor, transistor action, Base, emitter and collector currents and their relationship LED's.
9. Introduction To Digital Electronics :

Concept of binary numbers, Interconversion from binary to decimal and decimal to binary. Concepts of Gates (AND, NOT, OR).
10. Non-conventional energy sources:

- (a) Wind energy : Introduction, scope and significance, measurement of wind velocity by anemometer, general principle of wind mill.
- (b) Solar energy: Solar radiation and potentiality of solar radiation in India, uses of solar energy: Solar Cooker, solar water heater, solar photovoltaic cells, solar energy collector.

[DAS-23P] Applied Physics-II LAB

Note: Any 5 experiments are to be performed.

1. Determination of coefficient of friction on a horizontal plane.
2. Determination of 'g' by plotting a graph T^2 versus l and using the formula $g = 4\pi^2 / \text{Slope of the graph line}$
3. Determine the force constant of combination of springs in case of 1. Series 2. Parallel.
4. To verify the series and parallel combination of Resistances with the help of meter bridge.
5. To determine the velocity of sound with the help of resonance tube.
6. Determination of viscosity coefficient of a lubricant by Stoke's law.
7. Determination of E_1/E_2 of cells by potentiometer.
8. Determination of specific resistance by Carey Foster bridge.
9. Determination of resistivity by P.O.Box.
10. Verification of Kirchhoff's Law.
11. To draw Characteristics of p-n Junction diode.

[DEE-21] Basic Electrical Engg

1. Basic Terminology and their concepts
 - 1.1 Current, EMF, potential difference (Voltage), resistance, resistivity their units conductors & insulators, Insulation resistance of a cable.
 - 1.2 Effect of temperature on the resistance of conductors, semiconductors (C, Si, Ge) and insulators.
 - 1.3 Electrical power, energy and their units (SI), Heating effect of electric current and its practical examples.
 - 1.4 Relationship between electrical, mechanical and thermal SI units of work, power and energy.
2. D.C. Circuits
 - 2.1 Kirchhoff's laws.
 - 2.2 Simple numerical problems based on Kirchhoff's laws.
 - 2.3 Introduction to Thevenin and Superposition theorem, Norton's theorem
3. Batteries
 - 3.1 Construction, chemical changes during charging and discharging of lead acid cells.
 - 3.1(a) Indications of a fully charged battery.
 - 3.2 Capacity and efficiency of lead acid cell / battery.
 - 3.3 Charging of 6 V., 12 V. commercial batteries.
 - 3.3(a) Grouping of cells.
 - 3.4 Care and maintenance of commercial batteries.
 - 3.5 Problems/defects in lead acid batteries.
 - 3.6 Concept of Nickel-Iron and Nickel Cadmium Batteries.
 - 3.7 Concept of solid sealed maintenance free batteries (SMF batteries), Oxygen recombination principle.
4. Capacitors
 - 4.1 Concept of capacitor, types of capacity of parallel plate capacitor, Composite capacitor and effect of physical parameters.
 - 4.1 Energy stored in a capacitor, dielectric and its influence on capacitance of a capacitor, dielectric constant dielectric breakdown and dielectric strength. Dielectric loss.
 - 4.3 Series and parallel combination of capacitors.
 - 4.3(a) Capacitance of multi-plate capacitors.
 - 4.4 Variable capacitors.
 - 4.5 Charging and discharging of capacitors.
 - 4.6 Simple problems on capacitors.
5. Electromagnetism
 - 5.1 Concept of magnetic flux, flux density, magnetic field intensity, permeability and their units.
 - 5.2 Magnetic circuits, concept of reluctance and mmf and simple problems.

- 5.3 Analogy between electric and magnetic circuits.
- 5.4 B-H curve and magnetic hysteresis (No mathematical derivation).
- 5.5 Elementary ideas about hysteresis loss.
- 5.5(a) Lifting powers of a magnet.
- 6. Electromagnetic Induction
- 6.1 Faraday's laws of electromagnetic induction. Lenz's law, simple problem. Dynamically induced emf.
- 6.2 Self induced emf, inductance, its role in electrical circuits. Simple problems.
- 6.3 Mutually induced emf, mutual inductance, its role in electrical circuits. Simple problems.
- 6.4 Energy stored in magnetic circuit.
- 6.5 Rise and decay of current in inductors.
- 6.6 Force on a current carrying conductor placed in a magnetic field and its applications.
- 6.7 Elementary idea about eddy current loss.
- 7. A.C. Circuits
- 7.1 Recapitulation of terminology, instantaneous value, maximum (peak) value, cycle, frequency, alternate current and voltage. Difference between AC and DC.
- 7.2 Equation of an alternating voltage and current and wave shape varying sinusoidally.
- 7.3 Average and RMS value of alternating voltage and current. Importance of RMS value. Simple problems.
- 7.4 Concept of phase, phase difference and phasor representation of alternating voltage and current.
- 7.5. A.C. through pure resistance, inductance, capacitance, phasor diagram and power absorbed.
- 7.6 R-L series circuit, idea of impedance and calculations.
- 7.7 Apparent power, reactive power and active power, power factor, its importance and simple problems.
- 7.8 R-C series circuit, simple problems.
- 7.9 R-L-C series circuit, simple problems.
- 7.10 Solution of simple parallel A-C circuits by
 - (a) Phasor diagram method,
 - (b) Admittance method.
- 7.11 Solution of AC circuits series/parallel by j method.
- 7.12 Resonance (Series and parallel) and practical application, simple problems.
- 8. Poly-phase System
- 8.1 Introduction to poly-phase system. Advantage of three phase system over single phase system.
- 8.2 Star and Delta connections. Relationship between phase and line value of currents and voltage. Power in poly-phase circuits. Simple problems of balanced circuits only.

[DEE-21P] BASIC ELECTRICAL ENGG. LAB

- i) To show the variation of resistance of a lamp with temperature by plotting a V-I curve for 60W and 100W filament lamps.
- ii) To verify the Kirchhoff's laws.
- iii) To observe the B-H curve for a ferro-magnetic core on CRO.
- iv) To find the relationship between voltage and current for R-L series circuit for variable resistances & variable inductance.
- v) To determine the variation in the values of inductance of a coil for different positions of the movable iron core.
- vi) To measure the power factor in a single phase AC circuit by using voltmeter, ammeter & wattmeter.
- vii) To test a battery for charged and discharged condition and to charge a battery.
- viii) Verification of voltage and current relations in Star and delta connected systems.
- ix) To charge and discharge a capacitor and to show the graph on C.R.O.
- x) Verification of laws of capacitors in series and parallel.

[DEC-21] Electronics – I

1. Semiconductor Diodes

Semiconductor materials N type and P Type P.N. junction, its forward and reversed biasing; junction diode characteristics. Diode (P-N junction) as, half wave, full wave rectifier including bridge rectifier, relationship between D.C. output voltage and A.C. input voltage, rectification efficiency and ripple factor for rectifier circuits, filter circuits, shunt capacitor, series inductor, capacitor input filter. Different types of diodes, brief idea of characteristics

and typical applications of power diodes, zener diodes, varactor diodes, point contact diode, tunnel diodes, LEDs and photodiodes. Important specifications of rectifier diode and zener diode.

2. Bipolar Junction Transistor :

Concept of bipolar junction transistor, PNP and NPN transistors their symbols and mechanisms of current flow, explanation fundamental current relations. Concept of leakage current (I_{CBO}) effect of temperature on leakage current. Standard notation for current and voltage polarity; CB, CE, and CC configurations. Transistor input and output characteristics, concept of active, cut off and saturation region. Common emitter configuration: current relations in CE configuration, collector current in terms of base current and leakage current (I_{CEO}), relationship between the leakage current in CB and CE configuration, input and output characteristics, determination of dynamic input and output resistances and current amplification factor from the characteristics.

3. Single Stage Transistor Amplifier

Single stage CE amplifier with proper biasing circuit and its working as voltage amplifier. AC load line and its use in:

(a) Explanation of phase reversal of the output voltage with respect to input voltage. Introduction to tuned voltage amplifier.

4. FIELD EFFECT TRANSISTOR (FET), MOSFET & CMOS

A. FET :

- Construction, operation, characteristics and Biasing of Junction FET.
- Analysis of Single stage CB, CG and CD amplifier.

B. MOSFET :

- Construction, operation, characteristics and Biasing of MOSFET in both depletion and enhancement modes.
- Analysis of Single stage CB, CG and CD amplifier.

C. CMOS :

- Construction, operation, characteristics of CMOS in both depletion and enhancement modes.
- Use of CMOS as Inverter, Different Application of CMOS, CMOSIC.
- Comparison of JFET, MOSFET and Bipolar transistor.

5. MULTISTAGE & POWER AMPLIFIERS:

5.1 Need of multistage amplifier, different coupling schemes and their working, brief mention of application of each of the type of coupling.

5.2 Working of R.C. coupled and transformer coupled multistage amplifier, approximate calculation of voltage gain and frequency response for a two stage R-C coupled amplifier. Working principles of push pull amplifier circuits its advantages over single ended power amplifier.

6. Feedback in Amplifiers

Basic principles and types of feedback, derivation of expression for the gain of an amplifier employing feedback. Effect of negative feedback on gain, stability, distortion, and band width. (only physical explanation) typical feedback circuits:

(a) RC coupled amplifiers with emitter by-pass capacitor removed.

(b) Emitter follower, complementary symmetry power amplifier and its applications.

7. Regulated Power Supply

7.1 Concept of regulation.

7.2 Basic regulator circuits (using zener diode).

7.3 Concept of series and shunt regulator circuits.

7.4 Three terminal voltage regulator ICs (positive negative and variable) application. Block diagram, Pin configuration and working of popular regulator IC.

8. OSCILLATORS:

8.1 Application of oscillators.

8.2 Use of positive feedback/negative resistance for generation of oscillation, Barkhausen's criterion for oscillations.

[DEC-21P] ELECTRONICS I LAB

1. Semiconductor diode : identification of types of packages, terminals and noting different ratings using data books for various types of semiconductor diodes (germanium, point contact, silicon low power and high power and switching diode).

2. Rectifier circuits using semiconductor diode measurement of input and output voltage and plotting of input and output wave shapes:

i) Half wave rectifier

ii) Full wave rectifier (centre tapped and bridge rectifier circuits).

3. Plot the waveshapes of a full wave rectifier with shunt capacitor, series inductor, and filter circuit
4. Single stage common emitter amplifier circuit
 - i) Measurement of voltage gain at 1 KHZ for different load resistances.
 - ii) Plotting of frequency response of a single stage amplifier circuit.
 - iii) Measurement of input and output impedance of the amplifier circuit.
5. To measure the overall gain of two stage R.C coupled amplifier at 1 KHZ and note the effect of loading of second stage on the first stage.
- 6.(a) To plot the load Vs output power characteristic to determine the maximum signal input for undistorted signal output.
- (b) The above experiment is to be performed with single ended power amplifier, transistorized push pull amplifier. Complementary symmetry power amplifier.
7. To observe the effect of a by-pass capacitor by measuring voltage gain and plotting frequency response for a single stage amplifier.
8. To measure input and output impedance of a feedback amplifier with and without by-pass capacitor.
9. Measurement of voltage gain, input and output impedance and plotting of frequency response of an emitter follower circuit.
10. Plot the FET characteristics and determination of its parameters from these characteristics.
11. To test adjustable IC regulator and current regulator.
12. Identification of Some Popular IC of 74 and 40 series with Pin Number and other details.
13. Application and use of Multimeter, CRO, Audio Oscillator and Power Supply (D.C.)

[DDW-21] ENGINEERING DRAWING

1. Drawing, instruments and their uses.

1.1 Introduction to various drawing, instruments.

1.2 Correct use and care of Instruments.

1.3 Sizes of drawing sheets and their layouts.

2. (a) Lettering Techniques

1 Sheet

Printing of vertical and inclined, normal single stroke capital letters. Printing of vertical and inclined normal single stroke numbers. Stencils and their use.

(b) Introduction to Scales

2 Sheet

Necessity and use, R F Types of scales used in general engineering drawing. Plane, diagonal and chord scales.

3. Conventional Presentation:

2 Sheet

Types of lines, Conventional representation of materials, Thread (Internal and External), Conventional representation of machine parts, Welded joint.

4. (a) Principles of Projection

1 Sheet

Orthographic, Pictorial and perspective. Concept of horizontal and vertical planes. Difference between I and III angle projections. Dimensconing techniques.

(b) Projections of points, lines and planes.

2 Sheet

5 (a) Orthographic Projections of Simple Geometrical Solids

3 Sheet

Edge and axis making given angles with the reference planes. Face making given angles with reference planes. Face and its edge making given angles with reference planes.

(b) Orthographic views of simple composite solids from their isometric views.

(c) Exercises on missing surfaces and views

6. Section of Solids

2 Sheet

Concept of sectioning Cases involving cutting plane parallel to one of the reference planes and perpendicular to the others. Cases involving cutting plane perpendicular to one of the reference planes and inclined to the others plane, true shape of the section

7. Isometric Projection.

1 Sheet

Isometric scale Isometric projection of solids.

8. Free hand sketching

1 Sheet

Use of squared paper Orthographic views of simple solids Isometric views of simple job like carpentry joints

9. Development of Surfaces

2 Sheet

Parallel line and radial line methods of developments. Development of simple and truncated surfaces (Cube, prism, cylinder, cone and pyramid).

10. ORTHOGRAPHIC PROJECTION OF MACHINE PARTS:

3 Sheet

Nut and Bolt, Locking device, Bush Bearing

11. PRACTICE ON AUTO CAD :

2 Sheet

Concept of AutoCAD, Tool bars in AutoCAD, Coordinate System, Snap, Grid and Ortho mode. Drawing Command - Point, Line, Arc, Circle, Ellipse. Editing Commands - Scale, Erase, Copy, Stretch, Lengthen and Explode. Dimensioning and Placing text in drawing area. Sectioning and hatching. Inquiry for different parameters of drawing.

NOTE :

A. The drawing should include dimension with tolerance wherever necessary, material list according to I.S. code.

25% of the drawing sheet should be drawn in first angle projection and rest 75% drawing sheet should be in third angle figure

B. Practice on AutoCAD latest software is to be done in AutoCAD lab of Mechanical Engineering Department of the Institute.

SECOND YEAR

SEMESTER-III

DAS-31 APPLIED MATHEMATICS III

1. MATRICES:

1.1 Algebra of Matrices, Inverse: Addition, Multiplication of matrices, Null matrix and a unit matrix, Square matrix, Symmetric, Skew symmetric, Hermitian, Skew hermitian, Orthogonal, Unitary, diagonal and Triangular matrix, Determinant of a matrix. Definition and Computation of inverse of a matrix.

1.2 Elementary Row/Column Transformation: Meaning and use in computing inverse and rank of a matrix.

1.3 Linear Dependence, Rank of a Matrix : Linear dependence/independence of vectors, Definition and computation of a rank of matrix. Computing rank through determinants, Elementary row transformation and through the concept of a set of independent vectors, Consistency of equations.

1.4 Eigen Pairs, Cayley-Hamilton Theorem : Definition and evaluation of eigen values and eigen vectors of a matrix of order two and three, Cayley-Hamilton theorem (without Proof) and its verification, Use in finding inverse and powers of a matrix.

2. DIFFERENTIAL CALCULUS :

2.1 Function of two variables, identification of surfaces in space, coincides

2.2 Partial Differentiation : Directional derivative, Gradient, Use of gradient f , Partial derivatives, Chain rule, Higher order derivatives, Euler's theorem for homogeneous functions, Jacobians.

2.3 Vector Calculus : Vector function, Introduction to double and triple integral, differentiation and integration of vector functions, gradient, divergence and curl, differential derivatives.

3. DIFFERENTIAL EQUATION :

3.1 Formation, Order, Degree, Types, Solution : Formation of differential equations through physical, geometrical, mechanical and electrical considerations, Order, Degree of a differential equation, Linear, Nonlinear equation.

3.2 First Order Equations : Variable separable, equations reducible to separable forms, Homogeneous equations, equations reducible to homogeneous forms, Linear and Bernoulli form exact equation and their solutions.

3.3 Higher Order Linear Equation : Property of solution, Linear differential equation with constant coefficients (PI for $X = e^{ax}$, $\sin ax$, $\cos ax$, X_n , $e^{ax} V$, XV).

3.4 Simple Applications :LCR circuit, Motion under gravity, Newton's law of cooling,radioactive decay, Population growth, Force vibration of a mass point attached to spring with and without damping effect. Equivalence of electrical and mechanical system

4. INTEGRAL CALCULUS - II:

4.1 Beta and Gamma Functions :Definition, Use, Relation between the two, their use in evaluating integrals.

4.2 Fourier Series :Fourier series of $f(x)$, $-n < x < n$, Odd and even function, Half range series.

4.3 Laplace Transform :Definition, Basic theorem and properties, Unit step and Periodic functions, inverse Laplace transform, Solution of ordinary differential equations.

5. PROBABILITY AND STATISTICS :

5.1 Probability :Introduction, Addition and Multiplication theorem and simple problem.

5.2 Distribution :Discrete and continuous distribution, Binomial Distribution, Poisson Distribution, Normal Distribution.

[DEE-33] ELECTRICAL ENGINEERING-II

DETAILED CONTENTS

1.0 A.C. THEORY

1.1 Representation of sinusoidal quantities by phasors.

1.2 Physical explanation of the phase relationship between voltage and current when sinusoidal alternating voltage is applied across:-

- (a) Pure resistance,
- (b) Pure inductance and
- (c) Pure capacitance.

1.3 Explanation of inductive reactance, capacitive reactance and their significance.

1.4 Relationship between voltage and current when alternating voltage is applied to :-

- (a) Resistance and inductance in series,
- (b) Resistance and capacitance in series.

1.5 Solution and phasor diagrams for simple R-L-C circuits (Series and parallel); Impedance, Impedance triangle, phase angle.

1.6 Power in pure resistance, inductance and capacitance; power in combination of R-L-C circuits; power factor.

1.7 Active and reactive currents and their significance; practical importance of power factor.

1.8 Series and parallel resonance in R-L-C circuits, Q-factor of coils and capacitance.

2. THREE PHASE SUPPLY:

2.1 Elementary idea about 3-phase supply.

2.2 Star and delta connection. Relationship between phase and line voltage and currents.

2.3 Power and power factor in three phase system and their measurement.

2.4 Comparison between three phase and single phase supply.

3. TRANSFORMERS:

3.1 Principle of operation.

3.2 E.M.F equation, Voltage & Current relations.

3.3 Construction and applications of small transformers used in electronics and communication engg., construction of auto transformers, constant voltage transformer.

3.4 Phasor diagram of a transformer on load; Definition of regulation and efficiency; Elementary idea of losses in transformer, open circuit and short circuit test.

4. D.C. MACHINES:

(a) D. C. Generator: Working principle, constructional details, e.m.f equation, types of generators and their applications.

(b) D. C. Motor: Working principle, back e.m.f., types of D. C. motor and elementary idea of their characteristics, torque equation, methods of speed control (Description only).

(c) Starters for D.C. Machines

5. SYNCHRONOUS MACHINES:

(a) Alternators: Working principle, types of alternators, constructional details. e.m.f. equation, condition for parallel operation.

(b) Synchronous Motors: Working principle, construction details, vector diagram, effect of excitation on armature current and power factor, synchronous condenser.

(c) Application of synchronous machines.

6. INDUCTION MOTORS:

(a) Three Phase Induction Motor:

Working principle and constructional details, types of induction motor, slip ring and squirrel cage, slip in induction motors, speed torque characteristics, starting and speed control, application of induction motors in industry.

(b) Single Phase Induction Motor: Principle of operation and constructional details of single phase FHP induction motors (Split phase, capacitor start capacitor run, shaded pole, reluctance start, A.C. series, universal, hysteresis, servo and stepper motors their applications).

(c) Starters for Induction motors.

[DEE-33P] ELECTRICAL ENGINEERING-II LAB

List Of Experiments

1. To verify that in an A.C. circuit, the phasor sum (not the algebraic sum) of currents at any junction is zero.
2. To find the voltage-current relationship in a R-L series circuit and to measure power and power factor of the circuit.
3. To find for a filament lamp :-
 - (a) Variation of resistance with temperature.
 - (b) Variation of temperature with voltage.
 - (c) Variation of resistance with voltage.
 - (d) Variation of power with voltage.
4. To measure power and power factor in three phase system by two wattmeter method.
5. To determine the efficiency and regulation of a transformer by performing direct loading.
6. To measure the induced emf of separately excited D.C. generator as a function of field current.
7. To measure the terminal voltage of a separately excited D.C. generator as a function of load current.
8. To measure the terminal voltage of a D.C. shunt generator as a function of load current.
9. To measure the speed of a separately excited D.C. motor as a function of load torque at rated armature voltage.
10. To observe the difference in the starting current at switching on single phase capacitor start induction motor with :-
 - (a) The capacitor disconnected and
 - (b) The capacitor connected. Also to determine how to reverse the direction of rotation.
11. To start a Three Phase induction motor and to determine its slip at various loads.
12. To determine V curves of a synchronous motor.

[DEC-31]INDUSTRIAL ELECTRONICS AND TRANSDUCERS

DETAILED CONTENTS

1. THYRISTORS AND THEIR APPLICATIONS

- 1.1 Name, symbol and typical applications of members of thyristor family.
- 1.2 SCR, Triac and Diac-Basic structure, operation, V-I characteristics and ratings, gate circuits, ratings, triggering process and triggering circuits, turn off methods and circuits, selections of heat sinks, mounting of thyristor on heat sinks, basic idea of protection of thyristor circuits.
- 1.3 Operation, V-I characteristics, equivalent circuit and parameters of an UJT: Description of UJT relaxation oscillator, use of UJT relaxation oscillator for triggering thyristors.
- 1.4 Diac SCR and Triac switching circuits like automatic battery charger, voltage regulator, emergency light, alarm circuits, time delay relay circuits and circuits for over current and over voltage protection.
- 1.5 Single phase, various types of phase controlled rectifiers using SCR for resistive and inductive load explanation using waveshapes and appropriate mathematical equation (No derivation). A.C. phase control using SCRs and triacs, Application of phase controlled rectifiers and A.C. phase control circuits in illumination control, temperature control, variable speed drives using d.c. motors and small a.c. machines.
- 1.6 Half wave, full wave (including bridge) poly phase rectifiers using SCRs; explanation using wave shapes and formula (no derivation). Operation of three phase bridge controlled rectifier and its applications.
- 1.7 Principle of operation of basic inverter circuits, basic series and parallel commutated inverters, principle of operation of cycloconverter, choppers and dual converter, mention of applications.

2. PRINCIPLES AND APPLICATIONS OF INDUCTION AND DIELECTRIC HEATING (No Mathematical Treatment)

Introduction, importance of heating in industry, Principle of induction heating, Industrial applications of induction heating, Principle of dielectric heating, Industrial applications of dielectric heating.

3. TRANSDUCERS:

Basic idea and principle of operation and their use in measuring physical parameters of the following types of transducers. Transducer Typical Applications

- 3.1 Variable Resistance Type Potentiometric Resistance Displacement and force strain gauge. Torque and Displacement. Resistance Thermometer. Temperature. Thermistor. Temperature.
 - 3.2 Variable Capacitance Type Variable capacitance Displacement and pressure. pressure gauge. Capacitor microphone. Speed, noise Dielectric gauge. Liquid level & Thickness.
 - 3.3 Variable Inductance Type Differential Transformer. Pressure, force, displacement and position. Magnetostriction gauge. Force, pressure, sound.
 - 3.4 Piezoelectric Type Crystal Microphone, Crystal Oscillator
- #### **4. PROCESSING OF TRANSDUCER SIGNALS:**
- 4.1 Characteristics of instrumentation amplifiers in respect of input impedance, output impedance, drift, dc offset, noise,

gain common mode rejection, frequency response etc. Relating the suitability of these characteristics for amplifying signals from various transducers.

4.2 Block diagram and basic concept of open loop and closed loop systems.

5. OPTOELECTRONIC DEVICES:

5.1 Basic principle and characteristics of photo sources and photo detector, Photo resistors, photo diodes, photo transistors, photo electric cells, LCDs, LEDs and photocouplers.

5.2 LED- Material, Construction, Working, Power & Efficiency, Characteristics and modulation BW. Laser, Semiconductor Laser

5.3 Photo Detectors - Optical detection Principles, P-N photodiode, Avalanche Photodiode.

5.4 Electro-Optic Effect- Integrated optical Devices, Magneto- Optic Effect, Acousto-Optic Effect.

5.5 Sensors & Display Devices - Optical Fiber Sensors, Display Devices, LCD display, Numeric Display.

(Only Brief description of above)

LIST OF BOOKS

1. M. H. Rashid- " Power Electronics Circuits, Devices & Application"- P.H.I

2. J. Michael Jacob - " Power Electronics : Principle and Application" - Viks Publishing House Pvt. Ltd.

3. Singh Jasprit - " Optoelectronics An Introduction to Materials and Devices" - McGraw-Hill

4. C. S. Ranjan- "Instrumentation Devices & Systems"- Tata McGraw Hill.

[DEC-31P] INDUSTRIAL ELECTRONICS AND TRANSDUCERS LAB

List Of Experiments

1. Identification of various types of packages and terminals of various low and high power thyristors (SCR and Triac).

2. To determine and plot firing characteristics of SCR :-

(a) By varying the anode to cathode voltage.

(b) By varying the gate current.

3. Observing voltage waveshapes at various points of UJT relaxation oscillator circuit.

4. Observation of waveshapes at relevant points of the circuit of a single phase controlled rectifier using SCR and UJT relaxation oscillator.

5. To determine the firing characteristics of Triac in different mode i.e. Mode-I (plus), Mode-I (minus), Mode-III (plus), Mode-III (minus).

6. Observe the waveshapes and measure a.c. and d.c voltage at various points of a three phase bridge rectifier circuit.

7. Observe the waveshapes and measure a.c. and d.c. voltage at various points of a three phase SCR controlled bridge rectifier circuit.

8. Test an a.c. phase control circuit using triac and observe waveshapes and voltages at relevant points in circuit (while using for lamp intensity control and/or a.c. fan speed control).

9. To study the working of a single phase SCR/ transistor inverter circuit by observing waveshapes at input and output.

10. To measure force and pressure by using strain gauge transducer.

11. To observe the working of crystal microphone.

12. To observe the working principle of following devices in practical circuit :-

(a) Light Dependent Resistor (LDR).

(b) Photo electric cell.

(c) LED and LCDs.

(d) Avalanche Photodiode

(e) Optical fibre sensor

13. To measure voltages at different points of a circuit using a light sensitive device as ON-OFF control.

[DCS-32] PROGRAMMING IN C & C++

DETAILED CONTENTS

1. CONCEPT OF PROGRAMMING: Concept of Flowcharting, algorithm, programming, Structured Programming Various techniques of programming, Use of programming.

2. Programming in C: Data Types, Operators and Expressions; Input & Output printf, scanf, library Control Statement: IF- ELSE, While, For, Do- While, Switch; Functions and modular programming; Scope of variables, parameter passing, recursion, block structure; preprocessor statements; pointers and arrays; structures and unions; File handling.

3. CLASSES & OBJECT: What is a class, what is an object, constructors, types of object (external, automatic static, Dynamic objects) Metaclass, role of meta class. Scope of classes, array of objects, objects as a function argument.

4. Programming in C++: What is object-orientation, area of object technology, C++, getting to grips with C++(data types, escape sequence, characters, variables, operator, notation, Arrays, Function conditional statements. call by value, call by reference. Pointer : C++ memory map, dynamic allocation pointers, pointers with arrays. Structure, structure with arrays, passing, structure of function. Enumerated data types, Inherentance, apolymorphism & Overloading.

PROGRAMMING IN C & C++

List of Experiments

1. Exercises involving output and input format controls in Pascal.
2. Exercises involving control transfer statements in C & C++
3. Exercises with arrays & Pointers in C & C++.
4. Exercises with functions in C & C++.
5. Exercises with files in C & C++.

[DEC-35P] ELECTRONICS WORKSHOP

PART-A ELECTRICAL WORKSHOP

GENERAL OBJECTIVES

After the completion this course the learner will be able to

1. Become familiar with domestic and semi-domestic industrial wiring practice.

INSTRUCTIONAL OBJECTIVES

After completing this course the learner will be able to

1. Plan and Wire a small domestic building given the load requirement.
2. Specify the wiring planes of semi-insdustrial installations with three phase supply and a maximum of 5 KVA load.

Exercises To Be Performed No. of turns reqd.

1. Identification and study of commonly used 1 electrical material such as wires, cables, switches, fuses, coiling, roses, battens, cleats and allied items.
2. Identification and study of various tools 1 used in Electrical Workshop and safety measures.
3. Making connection of single lamp and three 1 pin plug socket to supply using batten wiring.
4. Making Electrical connection for staircase 1 wiring.
5. Making Electrical connection for a tube light 1 and door bell.
6. Wire a mains outlet pannel consisting of a 1 specified combination of 5 AMP; 15 AMP, Socket, Main switch, Indicating lamp and Fuse links.
7. Given the load requirements, prepare the 2 wiring diagram for a small Electronic/ Electrical Laboratory/ Workshop using energy meter, MDB and SDBS and details of sub-circuits, Protective device, cables/wires should be specified. The wiring should assume the availability of 3 phase 4 wire mains supply near the laboratory/workshop.

PART-B. ELECTRONICS WORKSHOP

GENERAL OBJECTIVE

After completion of instruction in this subject the student will :-

1. Develop skill in selection and use of commonly used tools, equipment, components in a given situation.
2. Develop skill in wiring, soldering and desoldering works.
3. Develop skill in tracing circuits of simple (analogue and digital) electronic assembly.

INSTRUCTIONAL OBJECTIVE

After completion of instruction in the subject the student will be able to :-

1. State the correct name and function of different tools and accessories, such as :-

Tools

Pliers, Wire cutter, Wire stripper, Tweezer, Soldering iron, Desoldering tools, Neon tester and Screw drivers.

Accessories

1. Including Tapes, Solders, Solders tips, Fluxes; De-soldering wick, Solder cleaning fluids, Sleeves, Tags.

2. Demonstrate the correct use of accessories mentioned in (1) above.

3. Selection and use of general purpose Electronic test and measuring equipemnt :-

- 3.1 Given any of the wavefrom generators specified in equipment type

(a) below with its controls set at random, the student should be able to operate/adjust the necessary control to demonstrate/any desired waveform on the appropriate measuring equipment, specified in

(b) below.

- 3.2 Given any measurement Parameter for being measures: equipment specified in Amplitude, Frequency phase

(b) below (with its Time Period, Rise and Fall controls set at random) time of pulse Waveform, common the student should be transistor parameters, circuit able to operate adjust resistance. the necessary controls to measure/display electrical parameter(s) such as specified on the right side margin.

3.3 Given different type of power supply mention in (c), the student should be able to find out the operating range and regulate the power supplies Equipment Type.

(a) Test Waveform Generator :- Audio oscillator, Function Generator, Signal Generator, Spectrum Analyzer.

(b) Measurement Equipment ; Single beam CRO, Double beam/Dual trace CRO, electronic and Digital multimeters, Transistor tester/Curve tracer, IC tester etc.

(c) Power Supply - UPS, Inverter, Different types of DC/AC power supplies

4. Students should be able to identify and use the item mention below (a), (b), (c) and (d).

(a) Various types of Single/Multicores, Insulated screened, Power type/ Audio/ Video/ General purpose wires and cables.

(b) Various types of plugs, sockets, connectors suitable general purpose audio, video use. Some of such connectors are : Banana plug and Sockets, ENC, DIN, UHF, VHF, Earphone connectors, Telephone jacks and similar male and female connectors and terminal strips.

(c) Various types of switches such as : Normal/miniature Toggle, Slide, Push button, Piano key rotary, SPST, DPDT, Band selector multiway, Master main switch.

(d) Various types of protective devices such as : Wire fuse, Cartridge fuse, Single/Multiple miniature circuit breakers over and under current relays.

5. Exercises to be performed :

i. Study and testing of different types of Resistor, Capacitor, Inductor, Diode, Transistor (BJT, FET, MOS, CMOS) and ICs (All Popular Families).

ii. Study of different processes by performing in assembling- Soldering, Desoldering, Cutting, Stripping and connecting.

iii. Study of equipment - their control and operation mentioned in no. 3 part of accessories.

iv. Study of the items mentioned in part 4-a,b,c,d by using them in different types of circuits.

v. Students should design and assemble at least seven working circuits (Full Fabricated Form) selecting at least three from each group A and B given below

Group A

1. Single Stage Amplifier

2. Halfwave and Full Rectifier

3. Filters

4. RC Coupled Amplifier

5. Power Amplifier (Push Pull)

6. Tuned Amplifier

7. Oscillator

8. Waveshaping Circuits

Group B

1. Clap Switch

2. Door Bell

3. Burglar Alarm

4. Porch Light

5. Water level Indicator

6. Fan regulator

7. 25 Kva Manual Stabilizer

8. Single band transistor radio receiver

Note :

1. The above list of Group B suggestive, more items may be added to the list depending upon students choice and materials availability but the item should belong consumers interest category.

2. Student should be encouraged for self market survey for each material.

PART-C PREPARATION OF PRINTED CIRCUIT BOARDS

Instructional Objective

*

After the completion of instruction in this area of the subject the learner will be able to :-

1. Acquire skill in silk screen printing techniques for the purpose of making the printed circuit boards.

2. Acquire knowledge of non dry-method of PCB making using photoprocessing techniques.

3. Acquire skill in preparing, checking, drilling and proper storing PCBs.

Suggested Task/Exercises No. of turns required.

1. Familiarisation with tools, equipment, 1 materials and processes of a single and double sided PCB making using direct etching method (Artwork to done by students) .
2. As above expect using photoprocessing 2 techniques. The initial exposure is to include the following
 - 2.1 Dark Room Practice.
 - (a) Exposure using UV light/daylight
 - (b) Developing (including dye developing)
 - (c) Fixing
 - (d) Printing (including contact printing)
 - (e) Enlarging/Reducing
 - 2.2 Techniques of photo-resist coating.
 - 2.3 Baking and cleaning procedures.
 - 2.4 Etching procedures.
 - 2.5 Procurement and storage of materials and equipment.
 - 2.6 Safety rules for PCB laboratory and darkroom.
3. Exercises in making simple single and double 2 sided PCB using direct etching method.
4. Exercises in making single and double sided 2 PCB using photoprocessing method.
5. Familiarisation with tools equipments, 2 materials and process of silk screen printing for PCB making.
6. Exercises in PCB making using silk screen 2 printing techniques.
7. Exercises in drilling, assembling and testing 1 of single and double sided PCB; proper storage of PCBs.

SEMESTER-IV

[DEC-42] NETWORKS, FILTERS & TRANSMISSION LINES

1. REVIEW OF NETWORK THEOREMS:

Review of the following, network theorem; superposition, Thevenin's Norton's and maximum power transfer.

2. NETWORKS:

2.1 One Port Network : Series and parallel tuned circuit, expression for their impedance at any frequency and at resonance in terms of Q and component values (L , C & R). Band width of tuned circuit in terms of resonance frequency and Q .

2.2 Two Port (Four Terminals Networks : Basic concept of the following terms :

(a) Symmetrical and asymmetrical networks.

(b) Balanced and unbalanced network,

(c) T-network, Ladder network, Lattice network, L Network, Bridge T-network.

(d) Representation of a two port " Block Box" in terms of Z , Y and H parameters and mention of application to transistor as a two port network.

3. SYMMETRICAL AND ASYMMETRICAL NETWORK :

3.1 Symmetrical Network : (a) Concept and significance of characteristic impedance, propagation constant, attenuation constant, phase shift constant and insertion loss.

(b) Expression for characteristic impedance, propagation constant, attenuation constant and phase-shift constant in terms of Z_o , Z_{oc} and Z_{sc} for the following

(i) T Network.

(ii) $n(\pi)$ Network.

3.2 Asymmetrical Network :

(a) Concept and significance of iterative impedance, image impedance, image transfer constant and insertion loss.

(b) The half section (L-section) : Splitting of symmetrical T & $n(\pi)$ sections into half sections, derivation of iterative impedance, image impedance open and short circuit impedance of half section.

3.3 Star-Delta Transformation : Equivalence of T and $n(\pi)$ network.

4. ATTENUATORS:

4.1 Units of attenuation (decibel and nepers)

4.2 General characteristics of attenuators.

4.3 Analysis and design of simple attenuator of following types

(a) Symmetrical T and π type.

(b) L type.

5. FILTERS:

5.1 Brief idea of the uses of filters networks in different communication system.

5.2 Connecting of low pass, high pass, band pass and band stop filters.

5.3 Theorem connecting attenuation constant α and characteristic impedance (Z_0) determination of cut off frequency constant K section.

5.4 Prototype filter section

(a) T and π low pass filter section. - Reactance frequency characteristics of low pass and its significance.

- Attenuation Vs frequency; phase shift Vs frequency characteristics impedance Vs frequency of T and π .

- Simple design problems of prototype low pass section.

5.5 Active Filter:

Basic Concept of active filter and comparison with passive. (a) Op. amp. integrator circuit, basic low pass active filter, First and Second order low pass Butterworth filter - Frequency response.

(b) Op. amp. differentiator circuit, basic high pass active filter, First and Second order high pass Butterworth filter - Frequency response.

(c) Basic concept of band pass filter, Wide and narrow bandpass active filter.

(d) Basic concept of band reject filter, wide and narrow band reject filter.

(e) All pass filter, Frequency response

5.6 Crystal Filter :

(a) Crystal and its equivalent circuit.

(b) Design properties of piezoelectric filters and their use.

5.7 Equalizers : General Introduction.

6. TRANSMISSION LINE:

6.1 Transmission lines and their application : Shapes of different types of transmission lines; including 300 ohm antenna feeder cable, 75 ohm co-axial cable, optical fibre cable, Also other different types of cables.

6.2 Distributed (or primary) constants of a transmission line equivalent circuit of infinite line;

6.3 Necessity of the concept of an infinite line; Definition of characteristic impedance of line ; concept of short line termination in Z_0 currents no voltages long an infinite line; graphical representation; propagation constant, attenuation and phase shift constant of the line.

6.4 Relationship of characteristics impedance, propagation constant, attenuation constant and phase constant in terms of distributed constants of the line, smith charts.

6.5 Conditions for minimum distortion and minimum attenuation of signal on the line; necessity and different methods of loading the communication lines.

6.6 Concept of reflection and standing waves on a transmission line; definition of reflection coefficient in terms of characteristic impedance and load impedance; Definition of standing wave ratio (SWR), relation between VSWR and

voltage reflection coefficient, maximum impedance on a line in terms of characteristic impedance and VSWR.

6.7 Transmission line equation; expression for voltage, current and impedance at a point on the lines for lines with and without losses. Expression for the input impedance of the line. Solving Transmission line problems using Smith Chart.

6.8 Input impedance of an open and short circuited line and its graphical representation.

6.9 Transmission line at high frequency, effect of high frequencies on the losses of a transmission line; Application of transmission line as a reactive components and impedance transformer (e.g. quarter wave and half wave transformer).

6.10 Principle of impedance matching using single stub; comparison of open and short circuit stubs.

6.11 Expression for characteristic impedance of open wire and coaxial lines (No derivation).

LIST OF BOOKS

1. J. P. Ryder- Network Filters & Transmission Line- PHI

2. A. Chakravorty- An Introduction to Network, Filters & Transmission Line- Dhanpat Rai & Co.

3. D. R. Chaudhry- Network Analysis- Dhanpat Rai & Co.

[DEC-42P] NETWORK, FILTERS AND TRANSMISSION LINES LAB

List of Experiment

1. Experimental verifications of the Thevenin's and Norton's theorem with an a.c. source.
2. Experimental verifications maximum power transfer theorem.
3. To measure the characteristics impedance of a symmetrical T/ π network.
4. To measure the image impedance of a given asymmetrical T/ π networks.
5. To design and measure the attenuation of a symmetrical T/ π type attenuator.
6. For a prototype low pass filter :
 - (a) Determine the characteristics impedance experimentally.
 - (b) Plot the attenuation characteristics.
7. For a prototype high pass filter :
 - (a) Determine the characteristics impedance experimentally.
 - (b) To plot the attenuation characteristic.
8. (a) To plot the impedance characteristic of a prototype band pass filter.
(b) To plot the attenuation characteristic of a prototype band pass filter.
9. (a) To plot the impedance characteristic of m-derived lowpass filter.
(b) To plot the attenuation characteristic of a m-derived high pass filter.
10. To design 1st order and 2nd order active LPF filter using IC 741 and draw the frequency response curve.
11. To design 1st order and 2nd order active HPF filter using IC 741 and draw the frequency response curve.
12. Measurement of characteristics of a short transmission line.
13. Measurement of L & C of lossless transmission line.
14. Measurement of Z_0 of lossless transmission line.
15. Measurement of Attenuation of lossless transmission line.

[DEC-43] ELECTRONIC DEVICES AND CIRCUITS

1. SINGLE STAGE AMPLIFIERS:

- 1.1 Transistor hybrid low frequency model in CE configuration, 'h' parameter and their physical significance, typical values of 'h' parameters and their determination by transistor characteristics.
- 1.2 Expressions for voltage gain, current gain, input and output impedance for a single stage CE amplifier circuit in 'h' parameters, appropriate approximations.

2. MULTISTAGE TRANSISTOR AMPLIFIERS:

- 2.1 Need of multistage amplifier, different coupling schemes and their working, brief mention of application of each of the type of coupling.
- 2.2 Working of R-C coupled and transformer coupled multistage amplifier, approximate calculation of voltage gain for a two stage R-C coupled amplifier.
- 2.3 Frequency response of R-C coupled and transformer coupled amplifiers and its physical explanation, definition and physical significance of the term as bandwidth, upper and lower cross over frequencies etc.
- 2.4 Direct coupled amplifier and its limitations differential amplifier typical circuits diagram and its working.

3. TRANSISTOR AUDIO POWER AMPLIFIERS:

- 3.1 Difference between voltage and power amplifier, importance of impedance matching in power amplifier, collector efficiency of power amplifier.
- 3.2 Typical single ended power amplifier and its working, graphical method for calculation of output power, heat dissipation curve and importance of heat sinks, class A, class B, class C amplifier (without derivation).

3.3 Working principle of push pull amplifier and circuits, its advantages over single ended power amplifier, cross over distortion in class B operation and its reduction, different driver stages for push pull amplifier circuit.

3.4 Working principle of complementary symmetry push pull circuit and its advantages.

3.5 Boot strap technique in amplifiers.

3.6 Transformer less audio power amplifiers and their typical application.

3.7 Mention of at least one popular IC with its block diagram, Pin configuration and its working of each type of power amplifier.

4. FEED BACK AMPLIFIERS:

4.1 Basic principle and types of feedback.

4.2 Derivation of expression for the gain of an amplifier employing feedback.

4.3 Effect of negative feedback on gain, stability, distortion and band width (Only physical explanation)

4.4 Typical feedback circuits :

(a) A.C. coupled amplifiers with emitter by-pass, capacitor removed.

(b) Emitter follower and its application, simple mathematical analysis for voltage gain and input impedance of above circuits.

5. TUNED VOLTAGE AMPLIFIERS:

5.1 Classification of amplifiers on the basis of frequency.

5.2 Review of basic characteristics of tuned circuits, (Series and Parallel)

5.3 Single and Double tuned amplifier, their working principles & frequency response (no mathematical derivation).

5.4 Staggered tuned amplifier and typical applications in brief.

5.5 Mention of at least one popular IC with its block diagram, Pin configuration and its working of each type of Tuned amplifier.

6. SINUSOIDAL OSCILLATORS:

6.1 Application of oscillators.

6.2 Use of positive feedback/negative resistance for generation of oscillation, Barkhausen's criterion for oscillations.

6.3 Different oscillator circuits, tuned collector, Hartley, Colpitts, phase shift, Wien's bridge and crystal oscillator and their working principles (no mathematical derivation).

6.4 Mention of at least one popular IC with its block diagram, Pin configuration and its working of each type of oscillators.

7. WAVESHAPING CIRCUITS:

7.1 General idea about different wave shapes.

7.2 Review of transient phenomena in R-C and R-L circuits.

7.3 R-C and R-L differentiating circuits and integrating circuits.

Their applications (physical explanation for square/rectangular input wave shapes only).

7.4 Diode clippers series and shunt biased type double clipper circuits.

7.5 Zener diode clipper circuits.

7.6 Use of transistor for clipping. Diode clamping circuit for clamping to negative peak, positive peak or any other levels for different input waveforms (e.g sine, square, triangular).

8. MULTIVIBRATOR CIRCUITS:

8.1 Ideal transistor switch; explanation using C.E. output characteristics, calculation of component values (collector and base resistors) for a practical transistor switch.

8.2 Transistor switching time. Use of speed up capacitor (Physical explanation).

8.3 Basic concept of working of collector coupled bistable, monostable and stable multivibrator circuits including principle of triggering.

8.4 Operation of Schmitt trigger, calculation of upper trigger potential (UTP) and lower trigger potential (LTP).

8.5 Mention of applications of multivibrators and Schmitt trigger. Its use as waveform generator.

8.6 Transistorised voltage controlled oscillator (basic) principle only.

8.7 Mention of at least one popular IC with its block diagram, Pin configuration and its working of each type of Multivibrator circuits.

9. OPERATIONAL AMPLIFIERS:

9.1 Specifications of ideal operational amplifier and its block diagram.

9.2 Definition of inverting and noninverting inputs, differential voltage gain and input and output offset, voltage input offset current, input bias current, commonmode rejection ratio (CMMR), power supply rejection ratio (PSRR) and slew rate.

9.3 Method of offset null adjustments, use of op.amp. as an inverter scale changer, adder, subtractor, differential amplifier, buffer amplifier, differentiator, integrator, comparator, Schmitt Trigger, Generation of Square and Triangular Waveform, log and anti-log amplifiers, PLL and its application and IC power amplifier.

9.4 IC OP-AMP Application :

Inverting/Noninverting VCVS integrators, Differentiators, CCVS and VCCS instrumentation amplifiers, Active filter (LP, HP and Notch), Oscillators. Log/Antilog modules, Precision rectifier, Peak detector, Sample and Hold Circuit, IC analog multiplier application, Analog multiplexer and demultiplexer.

10. Timer IC: Block diagram of IC timer (such as NE 555) and its working, use of 555 timer as monostable and astable multivibrator, and waveform generator.

11. Regulated Power Supply

11.1 Concept of regulation.

11.2 Basic regulator circuits (using zener diode).

11.3 Concept of series and shunt regulator circuits.

11.4 Three terminal voltage regulator ICs (positive negative and variable) application. Block diagram, Pin configuration and working of popular regulator IC.

11.5 OP-AMP regulators, IC regulators, Fixed Voltage regulators, (78/79, XX) 723 IC regulators (Current Limiting, Current Fold Back), SMPS.

12. Introduction to Microelectronics-

- Advantages of integration, Types of integrated circuits, Monolithic and Hybrid circuits.

- Different stages of fabrication of ICs- Epitaxial Growth, Oxidation and film deposition, Diffusion and Ion Implantation, Lithography & Etching. (Only brief idea of all)

- Masking, Selective doping, Fine-line lithography and isolation for Monolithic circuits.

- Introduction to monolithic device elements such as BJT, MOS, transistor and integration of other circuit elements.

- Very large scale integration (V.L.S.I.).

LIST OF BOOKS

1. Bhargava, Kulshreshtha & Gupta - "Basic Electronics & Linear Circuits" - Tata McGraw-Hill.

2. Malvino, A. P. - "Electronics Principles" - Tata McGraw-Hill.

3. Sedra, Adel S. Smith, Kenneth. C. "Micro Electronics Circuits" - Oxford University Press 5th Edition

[DEC-43P] ELECTRONIC DEVICES AND CIRCUITS LAB

List of Experiment

1. To measure the overall gain of two stage R.C. coupled amplifier at 1 KHz and note the effect of loading of second stage on the first stage.

2. To plot the frequency response of R-C coupled amplifier.

3. (a) To plot the load Vs output power characteristics to determine the maximum signal input for undistorted signal output.

(b) The above experiment is to be performed with single ended power amplifier; Transistorized push; pull amplifier; Complementary Symmetry power Amplifier.

4. To observe the effect of a by-pass capacitor by measuring voltage gain and plotting of frequency response for a single stage amplifier.

5. To measure input and output impedance of a feedback amplifier with and without by-pass capacitor.

6. Measurement of voltage gain input and output impedance and plotting of frequency response of an emitter follower circuit.

7. Measurement of resonant frequency, plotting of the response curve (i.e. graph between input frequency and impedance) and calculation of Q with the help of this curve for series and parallel resonant circuit.

8. To measure the frequency response of a single stage tuned voltage amplifier and calculation of the Q of the tuned circuit load.
9. Observe and plot the output waveshapes of ;
 - (a) R-C differentiating circuits.
 - (b) R-C integrating circuits for square wave input (observe the effect of R-C time constant of the circuits on the output waveshape for both the circuits).
10. (a) Observe the output waveforms of given biased and unbiased series and shunt clipping circuits, for positive and negative peak clipping circuits, for positive and negative peak clipping of a sine wave using switching diodes and D-C sources and compare it with input wave.
- (b) Observe the output wave shape of given double clipper circuit using diodes and D-C sources.
- (c) Observe the output wave shape of given zener diode and transistor clipper circuits for positive peak, negative peak and double clipping sine (or other) waveshapes.
11. To clamp square wave to their positive and negative peaks and to a specified level.
12. To measure I_c and V_{ce} for transistor when I_b is varied from zero to maximum value and measure the value of V_{ce} and I_c for saturation at a given supply, voltage and load.
13. To test a transistor schmitt trigger circuit, observe and plot the waveshapes at various points.
14. Use of Op-Amp. (for IC-741) as Inverting and non-inverting amplifier, adder, comparator, buffer, scale changer.
15. Simple working circuits using NE555.
16. To determine the range of frequency variation of a RC phase shift oscillator.
17. To test adjustable IC regulator and current regulator.
18. Identification, Pin configuration and basic working of different popular IC's - Exm.- Power amplifier, Oscillator, Tuned amplifier, Multivibrator, Timer.

[DEC-44] PRINCIPLES OF COMMUNICATION ENGINEERING

1. INTRODUCTION

- 1.1 Brief idea of various types of communication system.
- 1.2 Need of modulation and demodulation in communication system.
- 1.3 Types of modulation-Brief description and typical application of AM, FM, phase modulation and pulse modulation(PAM, PPM and PCM).

2. AMPLITUDE MODULATION

- 2.1 Derivation of expression for an amplitude modulated wave. Carrier and side bands, modulation index and depth of modulation.
- 2.2 Relative power distribution in carrier and side bands.
- 2.3 Elementary idea of DSB, DSB-SC, SSB, SSB-SC modulation and their comparison.
- 2.4 Vestigial side band modulation and its application.

3. FREQUENCY MODULATION

- 3.1 Derivation of an expression for frequency modulated wave and its frequency spectrum Modulation index, Maximum frequency deviation and deviation ratio.
- 3.2 Advantages and disadvantages of FM over AM in communication systems based on consideration of band width requirement and noise.

4. PHASE MODULATION

Expression of phase modulated wave and its comparison with frequency modulation. (Brief introduction only)

5. PULSE CODE MODULATION

- 5.1 Elementary idea of sampling theory and pulse modulation; Shannon's theorem and coding technique, Quantization (Brief idea only).
- 5.2 Time Division and frequency division multiplexing, CDMA, WDMA, FDMA and TDMA (Brief Idea Only).
- 5.3 PCM system, Types of PCM and its application.
- 5.4 Digital Modulation Techniques (ASK, FSK, PSK, DPSK) (Brief Idea Only).

6. PRINCIPLE OF AM MODULATORS

6.1 Working principles and typical application of

- Collector Modulator.
- Base Modulator.
- Balanced Modulator.

6.2 Single-Side-Band (SSB) generation and its typical applications.

7. PRINCIPLE OF FM MODULATORS

7.1 Working principle and applications of reactance tube modulator, varactor diode modulator and Armstrong phase modulator.

7.2 Limiter, pre-emphasis and de-emphasis in FM communication system.

8. DEMODULATION OF AM WAVES

8.1 Principle of demodulation of AM wave using diode detector circuit; concept of diagonal clipping and formula for RC time constant for minimum distortion (No derivation).

8.2 Comparison of typical diode detector circuits in a Radio and TV receiver.

9. DEMODULATION OF FM WAVES

9.1 Basic principles of detection of FM waves.

9.2 Foster-Jeeley discriminator and its working principles.

9.3 Working of Ratio-detector circuit and its advantage over Foster-Jeeley discriminator circuits.

9.4 Basic principle of Quadrature detection.

10. TRANSMITTERS

10.1 Classification of transmitters on the basis of power, frequency and modulation.

10.2 Block diagram of an AM transmitters and working of each stage. Low level and High level modulation.

10.3 Block diagram and working principle of reactance tube and Armstrong FM transmitters.

11. RADIO RECEIVER

11.1 Brief description of crystal and TRF radio receivers; Need for and principles of superheterodyne radio receiver.

11.2 Block diagram of super-heterodyne AM receiver, function of each block and typical waveforms at the input and output of each block.

11.3 Block diagram of an FM receiver, function of each block and wave/forms at input and output at different blocks.

12. ANTENNA AND PROPAGATION

12.1 Physical concept of radiation of electromagnetic energy from an antenna, relationship between the direction of electric and magnetic fields with direction of propagation; concept of polarisation of EM waves.

12.2 Electromagnetic spectrum and its various range VLF, LF, HF, VHF, UHF, Micro wave, Optical waves etc.

12.3 Definition and physical concepts of the terms used with antennas like point source, gain, power gain, directivity aperture, effective area, radiation pattern, (field strength, power and phase) beam angle, beam width and radiation resistance.

12.4 Types of antennas-Brief description, characteristics and typical applications of medium wave antenna, short wave antenna, HF antenna, VHF, UHF and Microwave antenna e.g., half wave dipole, ground plane, Yagi and ferrite rod antenna in transistor receiver. Brief idea about Rhombic antenna, dish antenna, Horn, Parabolic reflector and Lens antenna.

12.5 Antenna arrays-Brief description of broad side and end fire arrays, their radiation pattern and application (without analysis);

12.6 Basic idea about different modes of radio wave propagation ground wave propagation, space wave propagation and sky wave propagation, their characteristics and typical areas of application. (e.g. medium wave, short wave, TV communication.)

12.7 Explanation of the terms-critical frequency, maximum usable frequency (MUF) and skip distance.

13. Communication Media:- Telephone Lines, Twisted Pair Wire, Co-axial Cable, Fibre optics.

14. Modems - Basic working principle of modems and their application

15. Multiplexers- Digital Multiplexers- Synchronous and Asynchronous (Brief Idea Only).

List of Books

1. Simon Haykin-Communication System- John Wiley & Sons.
2. Kennedy & Davis- Electronic Communication System – TataMcgraw Hill.
3. Sombir Singh - Principle of Communication Engineering – JaiPrakesh Publication, Meerut

[DEC-44P] PRINCIPLE OF COMMUNICATION ENGINEERING LAB

List Of Experiments

1. (a) To observe an AM wave on CRO produced by a standard signal generator using internal and external modulation.
(b) To measure the modulation index of the wave obtained in above experiment.
 2. (a) To obtain an AM wave from a collector modulator circuit and observe the Am pattern on CRO.
(b) To measure index of modulation of the AM signal for different level of modulation signal.
 3. To obtain a FM wave from reactance tube modulator/voltage controlled oscillator (using 8038 or 566) circuit and measure the frequency deviation for different modulating signal.
 4. To obtain modulating signal from an AM detector circuit and observe the pattern for different RC time constants and obtain its optimum value for least distortion.
 5. To obtain modulating signal from a FM detector (Foster seely/ Ratio detector/ quadrature detector) Circuit (or using 2211 or PLL 565) and plot the detector characteristics.
 6. To obtain AM-SB from Balanced modulator.(BM025 may be used).
 7. To detect AM-SB by using SSB detector. (SL 640C may be used).
 8. To identify different stages of radio receiver and IC used at each stage and plot the sensitivity characteristics of a radio receiver and determination of the frequency for maximum sensitivity.
 9. To plot the selectivity characteristics of a radio receiver.
 10. To plot the fidelity characteristics of a radio receiver.
 11. (a) To plot the radiation pattern of directional and omnidirectional antenna.
(b) To plot the variation of field strength of radiated wave, with distance from a transmitting antenna.
 12. Tuning and alignment of radio receiver.
 13. Circuit tracing and fault finding of different stages of radio receiver.
 14. Simple demonstration, ASK, FSK and PSK through training kits
- NOTE :- Antenna simulator developed by TTTI can be used for this experiment.

[DEC-45] PRINCIPLE OF DIGITAL ELECTRONICS

1. INTRODUCTION TO DIGITAL ELECTRONICS:
 - 1.1 Basic difference between analog and digital signal.
 - 1.2 Application and advantages of digital signal processing.
2. NUMBER SYSTEM:
 - 2.1 Binary, Octal and Hexadecimal number system; conversion from decimal octal and hexadecimal to binary and vice-versa.
 - 2.2 Binary addition, subtraction, multiplication and division including binary points.
 - 2.3 1's and 2's complements method subtraction.
3. CODES, CODE CONVERSION AND PARITY:
 - 3.1 The 8421 and excess-3 codes; mention of other popular BCD codes.
 - 3.2 Addition of 8421, BCD coded numbers its limitations and excess-3 coded numbers.
 - 3.3 Gray code, Gray to binary conversion and vice-versa.
 - 3.4 Basic concept of parity, single and double parity and error detection.
4. LOGIC GATES:
 - 4.1 Definition, symbols and truth tables of NOT, AND, OR, NAND, NOR, EXOR Gates.
 - 4.2 Concept of negative and positive logic.
5. LOGIC SIMPLIFICATIONS
 - 5.1 Boolean algebra, Karnaugh-mapping (upto 4 variables) and simple application in developing combinational logic

circuits.

5.2 Implementation of logic equations with gates.

5.3 Use of NAND and NOR gates as universal gates.

6. LOGIC FAMILIES AND DIGITAL ICs:

6.1 Logic family classification :

(a) Definition of SSI, MSI, LSI, VLSI.

(b) Bipolar Logic, Diode Logic, Transistor Logic Inverter, TTL logic, MOS, CMOS logic, logic ECL

(c) Sub-classification of TTL and MOS logic families.

(d) Characteristics of TTL and MOS Digital gates delay, speed of noise margin, logic levels, power dissipation, FAN-IN, FAN-OUT, power supply requirements and comparison between TTL and MOS ICs.

6.2 Logic Circuits :

(a) Open collector and totem pole output circuit operation for a standard TTL, NAND gate.

(b) MOS circuit operation for a standard gate (NOR).

6.3 Tristate Switch : Normally open and normally closed switch.

6.4 Familiarisation with commercial digital IC gates, Their number identification and Pin configuration.

7. ARITHMETIC OPERATIONS:

7.1 Design of Exclusive or, Half adder and Half subtractor.

7.2 Design of Full adder circuits and its operation.

7.3 Design of Full subtractor circuits and its operation.

7.4 Some examples (circuits) of code convertors.

8. ENCODER, DECODERS & DISPLAY DEVICES ASSOCIATED CIRCUITS:

8.1 LED, LCD, seven segment display, basic operation of various commonly used types.

8.2 Four Decoder circuits for 7 segment display.

8.3 Basic decimal to BCD encoder circuits.

8.4 Use of decoders/driver ICs with reference to commercial ICs.

8.5 Basic Multiplexer and De-multiplexer

9. FLIP FLOPS:

9.1 Operation using waveforms and truth tables of following flipflops. RS, T, RST, D, JK, Master/Slave JK Flip Flops mention of commonly used ICs Flip flops.

10. COUNTERS:

10.1 Counters classification.

10.2 Binary and decade counters.

10.3 Divide by N counters.

10.4 Programmable asynchronous counters.

10.5 Down counters up/down counter operations.

10.6 Presettable asynchronous counters.

10.7 Difference between asynchronous and synchronous counters.

10.8 Ring counters with timing diagram.

10.9 Familiarization with commercial TTL/CMOS counters ICs.

11. SHIFT REGISTERS:

11.1 Introduction and Basic concepts including shift left and shift right.

11.2 Serial in serial out Serial in parallel out. Parallel in serial out. Parallel in parallel out.

11.3 Universal shift register.

11.4 Familiarisation with common TTL/CMOS ICs.

11.5 Buffer register, Tristate Buffer Register.

12. MEMORIES:

12.1 Classification according to the following heads.

(a) Volatile and non-volatile memories.

(b) Random access memories and sequential access.

(c) Semiconductor and non-semiconductor memories.

(d) Destructive and non-destructive memories.

12.2 Semi-conductor ROMs, PROMs, EPROM, SRAM, DRAM, Basic structure and working of CCD, R/W memory.

13. A/D AND D/A CONVERTORS:

13.1 Use of A/D and D/A converters.

13.2 Binary resistor network R-2R network.

13.3 D/A converter using R-2R.

13.4 UP, UP/Down counter type A/D converter.

13.5 Successive approximation.

13.6 Basic concepts of parallel A/D converter.

13.7 Two bit A/D converter.

14. ARITHMETIC CIRCUITS: Ideas About

14.1 Basic Arithmetic logic units applications.

14.2 Block diagram explanation of binary multiplier circuit.

List of Books

1. Malvino & Leach- Digital Principles & Application-Mcgraw Hill- 5th Edition.

2. Mano, M. Morris- Digital Logic and Computer Design- Prentice Hall (India)

[DEC-45P]PRINCIPLE OF DIGITAL ELECTRONICS-LAB

List of Experiments

1. Do at least 20 experiments familiarization with bread-board. Familiarization With TTL And MOS ICs.

2. Identification of IC-nos, Pin-nos, IC types.

3. To observe that logic low and logic high do not have same voltage value in input and output of logic gate.

4. To observe the propagation delay of TTL logic gate.

5. Observation of the difference between MOS and TTL gates under the following heads

(a) Logic levels.

(b) Operating voltages.

(c) Propagation delay.

Display Devices And Associated Circuits.

6. Familiarisation and use of different types of LEDs common anode and common cathode seven segment display.

7. Use of 7447 BCD to 7-segment decoder.

8. Verification of truth table for 2 Input NOT, AND, OR, NAND, NOR, XOR Gates. Design And Implementation Of Simple Logic Circuits.

9. To construct a 4-bit even/odd parity generator/checker using XOR gates and to verify their truth tables.

10. To construct half adder and half subtractor using XOR and NAND gates verification of their truth tables.

11. To construct a full adder circuit with XOR and NAND gates.

12. (a) Study of 3 bit adder circuit implemented with OR and NAND gates.

(b) To construct 4 bit adder and full subtractor using full adder chip 7480 and NAND gates.

13. (a) To verify the truth table of 4 bit adder IC chip 7483.

(b) To construct the 4 bit adder/2's complement subtractor using 7483 and NAND gates.

Flip Flops.

14. To verify the truth table for selected positive edge triggered and negative edge triggered F/F of J-K and D type.

Counters

15. To construct and verify truth table for asynchronous binary and decade

THIRD YEAR

SEMESTER-V

INDUSTRIAL MANAGEMENT AND ENTREPRENEURSHIP DEVELOPMENT

DETAILED CONTENTS

1. PRINCIPLES OF MANAGEMENT :

Definition of management, Administration organisation, Functions management, Planning, Organizing, Co-ordination and control, Structure and function of industrial organisations, Leadership- Need for leadership, Factors to be considered for accomplishing effective leadership, Communication -Importance, Processes, Barriers to communication, Making communication, Effective, formal and informal communication, Motivation - Factors determining motivation, Positive and negative motivation, Methods for improving motivation, Incentives, Pay promotion and rewards, Controlling - Just in time, Total quality management, Quality circle, Zero defect concept. Concept of Stress Management

2. HUMAN RESOURCE DEVELOPMENT :

Introduction, Staff development and career development, Training strategies and methods.

3. HUMAN AND INDUSTRIAL RELATIONS :

Human relations and performance in organisation, Understand self and others for effective behaviour, Industrial relations and disputes, Characteristics of group behaviour and Trade unionism, Mob psychology, Labour welfare, Workers participation in management.

4. PERSONNEL MANAGEMENT :

Responsibilities of human resource management - Policies and functions, Selection - Mode of selection - Procedure - training of workers, Job evaluation and Merit rating - Objectives and importance wage and salary administration - Classification of wage, Payment schemes, Components of wage, Wage fixation.

5. FINANCIAL MANAGEMENT :

Fixed and working capital - resource of capital, Shares, types preference and equity shares, Debenture types, Public deposits, Factory costing, Direct cost, Indirect cost, Factory overhead, Fixation of selling price of product, Depreciation- Causes, Methods.

6. MATERIAL MANAGEMENT :

Objective of a good stock control system - ABC analysis of inventory, Procurement and consumption cycle, Reorder level, Lead time, Economic order quantity, Purchasing procedure, Stock keeping, Bin card.

7. LABOUR, INDUSTRIAL AND TAX LAWS :

Importance and necessity of industrial legislation, Types of labour laws and dispute, Factory Act 1948, Payment of Wages Act 1947, Employee State Insurance Act 1948, Various types of taxes - Production Tax, Local Tax, Trade tax, Excise duty, Income Tax.

8. ENTREPRENEURSHIP DEVELOPMENT :

Concept of entrepreneurship, need of entrepreneurship in context of prevailing employment conditions of the country. Successful entrepreneurship and training for entrepreneurship development. Idea of project report preparation.

9. INTELLECTUAL PROPERTY RIGHTS :

Introduction to IPR (Patents, Copy Right, Trade Mark), Protection of undisclosed information, Concept and history of patents, Indian and International Patents Acts and Rules, Patentable and Nonpatentable invention including product versus Process.

ELECTRONIC INSTRUMENTS AND MEASUREMENTS

DETAILED CONTENTS

1. INTRODUCTION TO THE PROCESS OF MEASUREMENTS:

1.1 Review of the terms, accuracy, precision, sensitivity range and errors, difference between accuracy, precision and resolution.

1.2 Precaution against high frequency noise pick up and remedies, shielding and grounding (two terminal and three terminals).

1.3 Concept of selective wide band measurements.

2. MULTIMETERS:

2.1 Principle of measurement of D.C. voltage and D.C. current, A.C. voltage and A.C. current and resistance in a

multimeter.

2.2 Specifications of a multimeter and their significance.

2.3 Limitations with regards to frequency and impedance.

3. ELECTRONIC MULTIMETER:

3.1 Advantage over conventional multimeter for voltage measurement with respect to input impedance and sensitivity, principles of voltage, current and resistance measurements.

3.2 Specification of electronic multimeter and their significance.

4. A. C. MILLIVOLTMETER:

4.1 Types of AC millivoltmeters: Amplifier-rectifier and rectifier amplifier, block diagram and explanation of the above types of A.C. milli voltmeter.

4.2 Typical specifications and their significance.

5. CATHODE RAY OSCILLOSCOPE:

5.1 Construction of CRT, Electron gun, Electrostatic focusing and acceleration (Explanation only-no mathematical treatment) Deflection sensitivity, Brief mention of screen phosphor for CRT. Internal Block Diagram of CRO.

5.2 Explanation of time base operation and need for blanking during flyback, synchronisation.

5.3 Block diagram and explanation of a basic CRO and a triggered sweep oscilloscope, front panel controls.

5.4 Specifications of CRO and their significance.

5.5 Use of CRO for the measurement of voltage (D.C. & A.C.) frequency using Lissajous figure, time period, phase.

5.6 Special features of dual trace, delayed sweep and storage CROs (Brief mention only).

5.7 CRO probes including current probes.

5.8 Working Principle of Spectrum Analyzer.

6. AUDIO POWER METER:

6.1 Block diagram of an audio power meter.

6.2 Principles of working its application and high frequency limitations.

6.3 Scale conversion from power to db.

7. SIGNAL GENERATORS:

7.1 Block diagram explanation of laboratory type low frequency and RF signal generators, pulse generator and function generator.

7.2 Specification for low frequency signal generator, RF generator, pulse generator and function generator. Brief idea of testing specification for the above instruments.

7.3 Standard signal generator.

8. IMPEDANCE BRIDGES Q METERS:

8.1 D.C. and A.C. Bridges :

D.C. bridges- Wheat stone bridge, Kelvins bridges, Sensitivity- Null indicators. A. C. Bridges - Inductance bridges (Maxwell bridge), Capacitance bridges, Hays bridge, Anderson bridge, Schering bridge, Wein bridge, Twin network, Storage factor, Dissipation factor and their measurements.

8.2 Block diagram explanation and working principle of laboratory types (balancing type) RLC bridge. Specifications of a RLC bridge, Principle of digital RLC bridge.

8.2 Block diagram and working principles of a Q meter.

9. REGULATED POWER SUPPLY:

9.1 Block diagram of regulated power supply, IC based power supply.

9.2 Major specifications of regulated power supply, and their measurement (line and load regulation, output ripple and transients).

9.3 Basic working principles of switched mode power supply.

9.4 Concept of floating and grounded power supplies and their interconnections to obtain multiple output supplies.

9.5 Basic working principle of uninterrupted power supply

10. DIGITAL INSTRUMENTS:

10.1 Comparison of Analog and Digital instruments, characteristics of digital meter.

10.2 Working principle of Ramp, Dual slope and integrating type of digital voltmeter.

10.3 Block diagram and working of a digital millimeter.

10.4 Working principle of time interval frequency and period measurement using universal counter, frequency counter, time base stability and accuracy and resolution.

ELECTRONIC INSTRUMENTS AND MEASUREMENT LAB

List Of Practicals

1. Loading effect of a multimeter and its limitations to measure high frequency voltages.

2. Measurement of Q of a coil and its dependence on frequency using a Q meter.

3. Measurement of voltage, frequency, time period, phase angle and delay time using CRO : (use of Lissajous Figures).
4. Measurement of time period, frequency, average period using universal counter frequency counter.
5. To test a power supply for ripple, line and load regulation, Tracing of wave form, To find out operating range of power supply.
6. Measurement of rise, fall and delay time using a CRO.
7. Measurement of distortion of a LF signal generator using distortion factor meter.
8. Measurement of R.L. and C using a LRC bridge/universal bridge.

AUDIO AND VIDEO ENGINEERING

DETAILED CONTENTS

1. ELECTRO ACOUSTIC TRANSDUCERS:

1.1 Microphones-carbon, condensor, moving coil, crystal, ribbon and lavalier microphones, their construction and basic working principles, frequency response, impedance, sensitivity and directional patterns, typical applications of different types of microphones. Idea of other commercial microphones.

1.2 Loudspeakers-direct radiating and horn loader type their construction, working principles characteristics and applications. Baffles and Enclosures. Introduction to tweeters and woofers and crossover networks, Speakers column.

2. SOUND RECORDING:

Magnetic Recording :

2.1 Basic Idea about Sound Recording on Magnetic Tape and its reproduction.

2.2 Optical Recording of Sound :

Basic ideas of optical recording of sound on films and its reproduction

2.3 Digital Recording of Sound :

Basic ideas of Digital Recording and Reproduction of Sound. Basic concepts of sampling quantization, aliasing and encoding. formats of digital audio recording, basic of recording-Servo system. Material and formation of CD, Block diagram of audio CD player. Description of its main block.

3. HI-FI STEREO AND ITS SYSTEM:

3.1 General ideas about public address system and its block diagram.

3.2 Concept of Fidelity, noise and different types of distortions in an audio system. Stereophony, comparison of monophonic and stereophonic sound. Brief description of stereophonic recording on tape. Block diagram of hi-fi stereo system, Function of bass, Treble, Loudness and Balance control. Consequences of mismatch between amplifier output and speaker impedance. Need for a multi-speaker column. Cross over network in speaker columns.

4. VCD :

4.1 Basic principles of video recording and reproduction on discs by LASER technology.

4.2 Encoding of video signal, video format, Encoding of audio data for VCD.

4.3 Block diagram of VCD player and description of main block.

5. DVD :

5.1 Basic principles of video recording and reproduction on discs by Digital technology, Blue ray technology of recording

5.2 Basic concept of sampling and encoding, DVD Video format, DVD audio format.

5.3 Block diagram of DVD player and description of main component. Comparison of VCD and DVD.

6.A. INTRODUCTION TO TV COMMUNICATION:

6.1 Elements of telecast TV chain giving elementary idea of the role of TV camera, TV transmitter, propagation of signal, reception through antennas, TV receiver.

6.2 Brief mention of other types of TV communication such as CCTV, CATV, MATV, Satellite TV and their applications.

6.3 Brief mention of factors affecting range of TV coverage such as:-

(a) Line of sight propagation.

(b) Effect of earth's curvature.

(c) Receiving and transmitting antenna heights.

(d) Power of transmitter.

6.B. PRINCIPLES OF SCANNING AND FORMATION OF COMPOSITE VIDEO SIGNALS:

6.1 Basic of photoelectric conversion from scene to electrical signal through camera tube.

6.2 Sequential and interlaced scanning, line frequency field frequency.

6.3 Concept of :-

(a) Field and Frame.

- (b) Persistence of vision and flicker.
- (c) Horizontal and vertical resolution.
- (d) Picture element.
- (e) Relationship between interlacing and bandwidth.
- (f) Aspects ratio.
- (g) Relationship between line frequency, field frequency and video bandwidth.
- 6.4 Specifications of CCIR standard composite signal used in India, including the need of synchronisation blanking, and equalizing pulses signals (line and field) complete explanation of need for front and back porch in the VHF.
- 6.5 Frequency range of various bands and channels in the VHF range used in India.
- 6.6 Channel specifications :
- 6.6.1 Channel frequency limits, vision and sound carrier frequencies.
- 6.6.2 Need for VSB and VSB specifications.
- 6.6.3 Vision bandwidth, vision modulation types, sound bandwidth, sound modulation type, reasons for employing AM for vision FM for sound and negative modulation for TV transmission, Composite Video Signal.
- 7. CAMERA TUBES:
- 7.1 Brief description about vidicon and plumbicon camera tubes.
- 7.2 Basic concepts of Signal tube colour camera, its construction and working
- 8. TV TRANSMITTER AND RECEIVER:
- 8.1 Construction, Working and installation of Yagi Antenna
- 8.2 Block diagram of B/W TV transmitter and function of each block.
- 8.3 Block diagram of B/W TV receiver and function of each block.
- 8.4 Function of different control of a B/W TV receiver.
- 9. PICTURE TUBE:
- 9.1 Basic principle of operation and working B and W picture tube, its mounting and adjustment of Yoke.
- 9.2 Brief idea about delta gun and guns in line picture tube.
- 9.3 Construction and working of single gun(Trinitron) picture tube
- 9.4 Brief idea about shadow mask, convergence, degosing and purity.
- 10. FUNDAMENTAL OF COLOUR SIGNAL:
- 10.1 Basic idea about primary and complementary colour (Why, Red, Blue and Green are used as primary colour).
- 10.2 Need for compatibility with Black and White and Colour system.
- 10.3 Production of Luminance and colour difference signal.
- 11. COLOUR CAMERA :
- 11.1 Digital colour camera system.
- 11.2 Solid state imagers.
- 12. NTSC & PAL FUNDAMENTALS:
- 12.1 Basic principles of NTSC & PAL system.
- 12.2 Basic principle of QAM (Quadrature Amplitude Modulation)
- 12.3 Basic principle of PAL-S, PAL-D and Synchronous demodulation
- 12.4 Block diagram of NTSC and PAL coder and decoder, function of each block
- 13. VIDEO DISPLAY UNITS (VDU):
- 13.1 Block diagram and specifications of colour VDU and function of each block.
- 13.2 Interfacing of VDU with computers.
- 13.3 Basic idea about LCD/Plasma/LED monitor
- 13.4 Remote controlling of Electronic Devices (Basic Idea).
- 13.5 Basic Idea about 3DTV.

AUDIO AND VIDEO ENGINEERING LAB

List Of Practicals

1. Study of different features and Measurement of directivity of various types of microphones and loudspeakers. (Approximate).
2. Frequency response of crossover networks in speaker columns.
3. Installation and operations of PA system. (Preferably in auditorium).
4. Familiarity with the working of audio CD player and identification of main stages and components.
5. To study the operation and control of DVD player and identification of main stages and components.
6. Familiarisation with the physical layout, location of stages (transistors, ICs), major components, measurement of D.C. voltage & tracing of signal in B & W TV receiver. The student should be required to identify components from circuit diagram with physical layout of corresponding parts, marks hazardous areas.

7. Familiarisation with all controls and effects of adjustments of controls on the performance of a B & W TV receiver.
8. Testing of B & W CRT and associated circuits for defective operation, familiarity with pin connections, typical operating voltages and currents, typical circuit resistances of deflection coils.
9. Familiarisation with the physical layout, location of stages (transistors, ICs), major components, measurement of D.C. voltage & tracing of signal in Colour TV receiver. The student should be required to identify components from circuit diagram with physical layout of corresponding parts and marks hazardous areas.
10. Familiarisation with all controls and effects of adjustments of controls on the performance of a Colour TV receiver.
11. Installation of a TV receiver antenna and measurement of its impedance.
12. Fault finding in each stage of a B/W receiver.
13. Fault finding in each stage of a TV receiver.

MICROPROCESSORS AND APPLICATIONS

DETAILED CONTENTS

1. OVERVIEW OF MICROCOMPUTERS SYSTEM:

1.1 Functional block.

(a) CPU.

(b) Memory.

(c) Input/Out devices (Key board, Floppy drive, Harddisk drive, Tape drive, VDU, Printer, Plotter).

1.2 Concept of programme and data memory.

(a) Registers (general purpose).

(b) external memory for storing data and results.

1.3 Data transfer between registers.

1.4 Concept of tristate bus.

1.5 Control on registers.

2. MEMORY OF A MICROCOMPUTER:

2.1 Concept of byte organised memory.

(a) Address inputs.

(b) Address space.

(c) Data input/output.

2.2 Addressing and Address decoding.

(a) Memory system organisation.

(b) Partitioning of total memory space into small blocks.

(c) Bus contention and how to avoid it.

2.3 Memory chips.

(a) Types of ROM, RAM, EPROM, PROM.

(b) Read/Write inputs.

(c) Chip enable/select input.

(d) Other control input/output signals.

- Address latching.

- Read output.

- Address strobes.

(f) Power supply inputs.

2.4 Extension of memory.

- In terms of word length and depth.

3. C P U & CONTROL:

3.1 General microprocessor architecture.

3.1 Instruction pointer and instruction register.

3.2 Instruction format.

- Machine and Mnemonics codes.

- Machine and Assembly language.

3.3 Instruction decoder and control action.

3.4 Use of Arithmetic Logic Unit.

- Accumulator.

- Temporary Register.

- Flag flip-flop to indicate overflow, underflow, zero result occurrence.

3.5 Timing and control circuit.

- Crystal and frequency range for CPU operation.

- Control bus to control peripherals.

4. INTRODUCTION OF 8085 MICROPROCESSOR:

Evolution of Microprocessor, Register Structure, ALU, BUS Organization, Timing and Control.

5. INTRODUCTION OF 8086 MICROPROCESSOR:

Internal organization of 8086, Bus Interface Unit, Execution Unit, Unit, register, Organization, Sequential Memory Organization, Bus Cycle.

6. ASSEMBLY LANGUAGE PROGRAMMING :

Addressing Modes, Data Transfer, Instructions, Arithmetic and Logic Instruction, Program Control Instructions (Jumps, Conditional Jumps, Subroutine Call) Loop and String Instructions, Assembler Directives.

7. BASIC I/O INTERFACING :

Programmed I/O, Interrupt Driven I/O, DMA, Parallel I/O (8255-PPI, Centronics Parallel Port), Serial I/O (8251/8250, RS-232 Standard), 8259-Programmable Interrupt Controller, 8237-DMA Controller, 8253/8254-Programmable Timer/Counter, A/D and D/A conversion.

8. MEMORY INTERFACING :

Types of Memory, RAM and ROM Interfacing with Timing Considerations, DRAM Interfacing.

9. ADVANCE MICROPROCESSOR AND MICRO CONTROLLERS :

Brief idea of Microcontroller 8051, Pentium and Power PC

MICROPROCESSORS AND APPLICATIONS LAB

List Of Practicals

1. Assembly language programming :- Programming of simple problems.

2. Simple programming problems using 8085 and 8086 microprocessor.

Trainer kit to gain competence in the use of

(a) 8085 and 8086 Instruction set.

(b) Support chips of 8085 and 8086.

FIELD EXPOSURE

SEMESTER-VI

ENVIRONMENTAL EDUCATION & DISASTER MANAGEMENT

1. INTRODUCTION :

- Basics of ecology, Ecosystem, Biodiversity Human activities and its effect on ecology and eco system, different development i.e. irrigation, urbanization, road development and other engineering activities and their effects on ecology and eco system, Mining and deforestation and their effects.

- Lowering of water level , Urbanization.

- Biodegradation and Biodegradability, composting, bio remediation, Microbes .Use of biopesticides and biofungicides.

- Global warning concerns, Ozone layer depletion, Green house effect, Acid rain,etc.

2. POLLUTION :

Sources of pollution, natural and man made, their effects on living environments and related legislation.

2.1 WATER POLLUTION :

- Factors contributing water pollution and their effect.

- Domestic waste water and industrial waste water. Heavy metals, microbes and leaching metal.

- Physical, Chemical and Biological Characteristics of waste water.

- Indian Standards for quality of drinking water.

- Indian Standards for quality of treated waste water.

- Treatment methods of effluent (domestic waste water and industrial/ mining waste water), its reuse/safe disposal.

2.2 AIR POLLUTION :

Definition of Air pollution, types of air pollutants i.e. SPM, NOX, SOX, CO, CO₂, NH₃, F, CL, causes and its effects on the environment.

- Monitoring and control of air pollutants, Control measures techniques. Introductory Idea of control equipment in industries i.e.

A. Settling chambers

B. Cyclones

C. Scrubbers (Dry and Wet)

D. Multi Clones

E. Electro Static Precipitations

F. Bog Fillers.

- Ambient air quality measurement and their standards.

- Process and domestic emission control

- Vehicular Pollution and Its control with special emphasis of Euro-I, Euro-II, Euro-III and Euro IV.

2.3 NOISE POLLUTION :

Sources of noise pollution, its effect and control.

2.4 RADISACTIVE POLLUTION :

Sources and its effect on human, animal, plant and material, means to control and preventive measures.

2.5 SOLID WASTE MANAGEMENT :

Municipal solid waste, Biomedical waste, Industrial and Hazardous waste, Plastic waste and its management.

3. LEGISLATION :

Preliminary knowledge of the following Acts and rules made thereunder-

- The Water (Prevention and Control of Pollution) Act - 1974.

- The Air (Prevention and Control of Pollution) Act - 1981.

- The Environmental Protection (Prevention and Control of Pollution) Act -1986. Rules notified under EP Act - 1986
Viz.

- # The Manufacture, Storage and Import of Hazardous Chemical (Amendment) Rules, 2000

- # The Hazardous Wastes (Management and Handling) Amendment Rules, 2003.

- # Bio-Medical Waste (Management and Handling) (Amendment) Rules, 2003.

- # The Noise Pollution (Regulation and Control) (Amendment) Rules, 2002.

- # Municipal Solid Wastes (Management and Handling) Rules, 2000.

- # The Recycled Plastics Manufacture and Usage (Amendment) rules, 2003.

4. ENVIRONMENTAL IMPACT ASSESSMENT (EIA) :

- Basic concepts, objective and methodology of EIA.

- Objectives and requirement of Environmental Management System (ISO-14000) (An Introduction).

5. DISASTER MANAGEMENT :

Definition of disaster - Natural and Manmade, Type of disaster management, How disaster forms, Destructive power, Causes and Hazards, Case study of Tsunami Disaster, National policy- Its objective and main features, National Environment Policy, Need for central intervention, State Disaster Authority- Duties and powers, Case studies of various Disaster in the country, Meaning and benefit of vulnerability reduction, Factor promoting vulnerability reduction and mitigation, Emergency support function plan. Main feature and function of National Disaster Management Frame Work, Disaster mitigation and prevention, Legal Policy Frame Work, Early warning system, Human Resource Development and Function, Information dissemination and communication.

MODERN COMMUNICATION SYSTEMS

DETAILED CONTENTS

1. INTRODUCTION TO COMMUNICATION SYSTEM :

Basic idea of telegraphy, telephonic, digital, microwave, fibre optics, stellite, mobile and data communication.

2. TELEGRAPHY AND TELEPHONY:

A. Facsimile transmission- Elementary idea of Fax machine and its operation, Transmission and Receiving process

B. Telephone component- Construction and working of transmitter and receiver components, parts, circuit and working of subscriber's push button telephone sets.

C. Brief idea of Automatic Exchanges

D. Brief Idea of Electronic Exchanges and PCO.

3. DIGITAL SWITCHING SYSTEM :

Salient feature, architecture and services of C-DOT 128, C DOT 256, C-DOT 512, EWSD (Electronic Digital Switching Network, OCB-283.

4. OPTICAL COMMUNICATION:

4.1 Introduction : Block diagram of optical fiber communication system, advantages of optical communication

4.2 Optical Fibre : Structure of optical wave guide, light propagation in optical fiber, Ray and wave theory, Modes in optical fiber, Step and Graded index fibers.

4.3 Transmission Characteristics of Optical Fibers : Signal degradation in optical fibers, Attenuation losses in optical fibers. Dispersion and pulse broadening in different types of fibers, Modal birefringence and polarisation maintaining fibers.

- 4.4 Principle laser action types of lasers, fabrication and characteristics of semiconductor lasers and L.E.D.'s
- 4.5 Requirements for Photo detectors, Types of photo detectors, Characteristics of photo detectors. Principle of APD and Pin diodes. Phot transistor and Photo Conductors.
- 4.6 Components of an optical fiber communication system, Digital and Analog Optical Communication System.
- 5. DIGITAL COMMUNICATION:**
- 5.1 Elements of Digital Communication and information theory :
Model of a digital communication system, Logarithmic measure of information. Source coding fixed in and variable length code words. Hartely-Shannon law for channel.
- 5.2 Sampling Theory and Pulse Modulation : Sampling theorem, Signal reconstruction in time domain. Types of analog pulse modulation, Method of generation and detection of PWM, PNM and PPM.
- 5.3 Waveform Coding Technique : Quantization, Quantization noise, Encoding and Pulse code modulation, Differential pulse code modulation, Delta modulation, Comparison of PCM and DM.
- 5.4 Digital Multiplexing : Fundamentals of time division multiplexing electronic commutator.
- 5.5 Digital Modulation Techniques : Types of digital modulation, Wave forms for amplitude, Frequency and phase shift keying, Method of generation and detection of coherent and noncoherent binary ASK,FSK & PSK, Differential phase shift, Quadrature modulation techniques. (QPSK and MSK) Probability of error and comparison of various digital modulation techniques.
- 5.6 Error Control Coding : Error free communication over a noisy channel, Hamming sphere, Hamming distance and Hamming bound, Relation between minimum distance and error detecting and correcting capability.
- 6. SATELLITE COMMUNICATION:**
- (i) Introduction, historical background and basic Concepts of satellite communication. Elements of satellite communication link.
- (ii) Geostationary orbits, Orbit mechanisms and launching of satellite
- (iii) Satellite space craft- Satellite sub system, Tracking and Command, Communication subsystem, Transponders, Space Craft antenna
- (iv) Satellite Channel and Link Design : Design of down links and uplinks
- (v) Earth stations technology : Earth Station Design, Earth Station Tracking, Low noise amplifiers.
- (vi) Multiple access techniques :Frequency Division Multiple Access (FDMA), FDM/FM/FMFDMA, Time division, Multiple Access, Frame Structure and Synchronization, Code division, Multiple Access, random Access.
- (vii) Introduction to DTH system
- 7. MOBILE COMMUNICATION :**
- Evaluation of mobile communication, A simplified reference model for mobile communications. A brief introduction of frequency for radio transmission, signals, propagation, Multiplexing, Modulation, Spread spectrum, Cellular system. Medium Access Control : Introduction To MAC, Advance Mobile Phone. Introduction to GSM(Global System For Mobile Communication), GPRS, GPS, Enable Positioning System. System Architecture, Protocol Architecture, Physical Layer and MAC layer. Mobile Networks
- 8. DATA COMMUNICATION :**
1. Data Transmission Basics : Review of digital data analog modulation and digital formats. Data rates, Baud Rates, Channel capacity, Mediums for communication, Synchronous and asynchronous data communication.
2. ISO-OSI model and TCP/IP model of network, Protocols and services. Connection oriented and connectionless services, their interpretation at different layers. Quality of services, Design issue for different layers.
3. Data Links Layer Design Issues : Services provided to network layer froming: Necessity and techniques. Error control feature and review of techniques.
4. IEEE 802 standards for computer networks.
5. Brief idea of network layer, transport layer.
6. Internet and ISDN services.

MODERN COMMUNICATION SYSTEMS LAB

List Of Practicals

1. Study of FAX machines and its working.
2. To study the parts of telephone hand set :
 - (a) Frequency response of telephone receiver.
 - (b) To observe the wave form of impulses by dialling a number.
3. Visit and study of Digital Switching System.
4. Visit and study of Satellite transmission system.
5. Demonstration of sampling, FSK and PSK by simple experiment.
6. Demonstration of optical fibre communication through simple kits.
7. Study of working of mobile phones and its services.

8. Study and use of ISDN and Internet services.
9. Testing and fault finding of mobile phone and its service.
10. Visit and study of cellular base station.
11. Study of DTH system

OPTICAL FIBRE ENGINEERING

DETAILED CONTENTS

1. FUNDAMENTAL OF OPTICS :

1. Nature of Light :
 - 1.1 Electromagnetic nature of light.
 - 1.2 Principle of reflection, refractions, polarization.
 - 1.3 Basic principle of optical communication.
2. Introduction To Optical Fibre :
 - 2.1 Classification of fibre
 - 2.2 Physical structure.
 - 2.3 Electromagnetic mode theory for optical propagation - Electromagnetic waves, Modes in planar guide, Modes in cylindrical fiber phase and group velocity.

2. OPTICAL DEVICE :

1. Optical Sources :
 - 1.1 Direct and indirect band gap semiconductors.
 - 1.2 Internal and external quantum efficiency.
 - 1.3 Principle, characteristics and construction of LED.
 - 1.4 Semiconductor Lasers - Laser action, PN junction laser, Fabry- Perot resonators.
2. Detectors :
 - 2.1 Introduction
 - 2.2 Photodiode- Material and types.
 - 2.3 Avalanche Photo Diode (APD), PIN diode.
 - 2.4 Temperature effect on avalanche gain, noise in APD.
 - 2.5 Photo transistor, PIN-FET, Photo darlington.
 - 2.6 Response time, BW, Noise equivalent power, responsivity.
 - 2.7 Spectral response, dark current and quantum efficiency.
3. connectors, Splicers and Splitters :
 - 3.1 Need of connectors.
 - 3.2 Types of connectors.
 - 3.3 Single and multimode fiber connectors.
 - 3.4 Need and splicing.
 - 3.5 Types of splicing.
 - 3.6 Different splicing techniques.
 - 3.7 Splitters.
4. Couplers and Cable
 - 4.1 Need and types of couplers.
 - 4.2 Source of fiber couplers, Fiber to Fiber couplers, Fiber to detector couplers.
 - 4.3 Intrinsic and Extrinsic coupling loss.
 - 4.4 Reasons and types - Under ground, Under sea and over head.
 - 4.5 Elements of cable structure and its characteristics.
 - 4.6 Cable installation and design consideration.
 - 4.7 Cable jacketing, cable laying, Transport and handling.

3. OPTICAL MEASUREMENT :

- 3.1 Introduction.
- 3.2 Transmission loss measurements - Fiber attenuation, Fiber absorption loss measurement, Fiber scattering loss measurement.
- 3.3 Fiber dispersion measurements - Time Domain and Frequency Domain measurements.
- 3.4 Fiber cut off wave length, Fiber numerical aperture measurements.

4. OPTICAL COMMUNICATION :

- 4.1 Introduction of light wave.
- 4.2 Types of modulation, ON-OFF modulation
- 4.3 Analog and Digital transmission.
- 4.4 Audio Video and Data transmission.
- 4.5 Computer communication using RS 232 Port.
- 4.6 Coherent System.

OPTICAL FIBRE ENGINEERING LAB

List Of Practical's

1. Study of reflection of light.
2. Study of LED characteristics.
3. Study of Laser characteristics
4. Study of Optical detector characteristics
5. Study of different connectors.
6. Study of different splices.
7. Study of different couplers and splitters.
8. Measurement of connectors loss.
9. Measurement of splice loss.
10. Measurement of coupling loss.
11. Study of dispersion loss in Fiber.

MICROWAVE & RADAR ENGINEERING

DETAILED CONTENTS

1. E.M. WAVE THEORY:
 - 1.1 Boundary Condition and different forms of Maxwell Equation
 - 1.2 Concept of polarization of EM waves.
 - 1.3 Concept of the electromagnetic radiation and propagation.
2. ANTENNA :

A study of Microwave antenna
3. MICROWAVE:
 - 3.1 Introduction to microwave and its applications, classification on the basis of its frequency band according to ITU standards.
 - 3.2 Effects of interelectrode capacitance, lead inductance and transit time on the signal frequency performance of conventional operations.
 - 3.3 Construction, Operating Principles, Performance characteristics and Applications of the following -
 - (a) Microwave Tubes- Multi-cavity Klystron, Multi-cavity Magnetron, Reflex Klystron, Travelling wave tube and BWO.
 - (b) Microwave Semiconductor Devices - PIN, Tunnel Diode, IMPATT and TRAPATT and Gun diode .
 - 3.4 Different types of waveguides and their applications. Propagation constant of a rectangular waveguide, cut off wavelength, guide wavelength. (No Mathematical Derivation)
 - 3.5 Microwave components-Tees, Bends, Matched termination, Detector mount, Slotted section, directional coupler, Circulator and duplexer-their constructional features characteristics and application.
 - 3.6 Microwave antennas-horn and parabolic dish antennas-their characteristics and typical applications.
 - 3.7 Block diagram and working principles of microwave systems.
 - 3.8 Microwave power measurements thermal converters.
 - 3.9 Planning of microwave links-Line of sight, Fresnel zones reflecting surfaces and fade margin.
 - 3.10 Troposcatter links-Basic idea only.
4. RADAR SYSTEMS:
 - 4.1 Introduction to Radar, its various application. Radar range equation (No Derivation) and its application.
 - 4.2 Block diagram and operating principle of basic pulse radar, concept of ambiguous range.
 - 4.3 Block diagram, operating principle of CW (Doppler) and FMCW radars and their application.
 - 4.4 Block diagram and operating principle of MTI radar.
 - 4.5 Radar display-PPI.
5. RADIO AIDS TO NAVIGATION:
 - 5.1 Application of loop antenna in direction finding, Errors of a loop antenna.
 - 5.2 Description of different navigational system-VHF omnirange

(VCR). Distance measuring equipment (DME), Long Rang Navigational (LORAN), Instrument Landing System (ILS) and Ground Control Approach.

6. SATELLITE COMMUNICATION:

6.1 Basic idea passive and active satellites.

6.2 Meaning of the terms Orbit, Apogee and Perigee.

6.3 Geo-stationary satellite and its need.

6.4 Block diagram and explanation of a satellite communication link.

7. FACSIMILE TRANSMISSION:

7.1 Basic concept.

7.2 Specifications of facsimile transmitter and receiver.

7.3 Block diagram & function of each block.

PROJECT

GENERAL OBJECTIVE:

Purpose of the project work is :

(i) To develop abilities of diagnosing problems.

(ii) To develop the abilities to :

(a) Make literature survey.

(b) Design/develop/frabricate/test simple circuits.

(c) Prepare documents for electronic work.

(d) Work as a team.